



MICROWAVE OVEN CONTROLLER DESIGN

A THESIS SUBMITTED IN PARTIAL FULFILLMENT OF THE REQUIREMENT FOR BACHELOR OF SCIENCE IN ELECTRICAL AND ELECTRONICS ENGINEERING

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This is to certify that the work presented in this thesis is an outcome of the investigation carried out by the authors under the supervision of prof.Dr.Md.Ashraful Hoque, Department of Electrical and Electronics Engineering, Islamic University of Technology (Bangladesh).

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ABSTRACT

Micro controller plays an important role in industries as well as in our day-to-day life.

They are programmable devices which are used to control working principles of technologies or functionalities of different application that has been designed based on each and every single instruction that has been given to the Micro controller using assembly language (MPLAB/simulation and Proteus in our project, to design control unit if Microwave oven using micro controller PIC16F872A), and provides desired functions and proper directions in industries.

They are also an indispensable part of our daily lives. An average home in Australia, Asia, Europe, Africa and America using these technology.

Microcontroller is considered as a basic device or equipment in software engineering and programming.

The aim of this thesis is to introduce students to the modeling and designing instructions of control unit of micro wave oven using micro controller for different operation on different components, based on MPLAB and PROTEUS and to use computer simulation as a tool for conducting procedures and control studies.

From reading theory the dynamic behavior and interactions that are often not readily apparent and feasible that is why simulation can be very helpful in gaining insights to the different behaviors.

Next to having an actual system to experiment on, simulation is often chosen by engineers to study transient and control performance or to test conceptual designs.

MPLAB is used because of the short learning instruction that most students require to start using it, its wide distribution, and its general-purpose nature. This will demonstrate the advantages of using MPLAB for analyzing micro controller instructions power system steady state behavior and its capabilities for simulating transients in power systems and power electronics, including control system dynamic behavior.

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Chapter 1

Introduction

The microwave oven is one of the great invention of the 20th century- millions of homes in world have one. A typical microwave oven uses between 500 and 1000 W of microwave energy at 2.45 GHz to heat the food. This heating is caused mainly by the vibration of the water molecules. Thus plastic, glass, or even paper containers will heat only through conduction from the hot food. There is little transfer of energy directly to these materials. This also means that the food does not need to be a conductor of electricity (try heating a cup of distilled water) and that electromagnetic induction (used elsewhere for high frequency non-contact heating) is not involved.

What is significant about 2.45 GHz? Not that much. Water molecules are not resonant at this frequency. A wide range of frequencies will work to heat water efficiently. 2.45 GHz was probably chosen for a number of other reasons including not interfering with existing EM spectrum assignments and convenience in implementation. In addition, the wavelength (about 5 inches) results in reasonable penetration of the microwave energy into the food. The 3 dB (half power) point is about 1 inch for liquid water - half the power is absorbed in the outer 1 inch of depth, another 1/4 of the power in the next inch, and so forth.

"Industrial ovens still often operate at 915 MHz and other frequencies near 6 GHz are also used.

Water has numerous resonances over the entire spectra range, but the lowest frequency resonance is the rotational resonance is around 24 GHz. Other resonances occur in the millimeter wave range through the infrared.

Since the oven chamber cavity is a good reflector of microwaves, nearly all the energy generated by the oven is available to heat the food and heating speed is thus only dependent on the available power and how much food is being cooked. Ignoring losses through convection, the time to heat food is roughly proportional to its weight. Thus two cups of water will take around twice as long to bring to a boil as one.

Heating is not (as popularly assumed) from the inside out. The penetration depth of the microwave energy is a few cm so that the outside is cooked faster than the inside. However, unlike a conventional oven, the microwave energy does penetrate these few cm rather than being totally applied to the exterior of the food. The misconception may arise when sampling something like a pie filling just out of the microwave (or conventional oven for that matter). Since the pie can only cool from the outside, the interior filling will appear to be much hotter than the crust and will remain that way for a long time.

One very real effect that may occur with liquids is superheating. It is possible to heat a pure liquid like water to above its boiling point if there are no centers for bubbles to form such as dust specks or container imperfections. Such a superheated liquid may boil suddenly and violently

upon removal from the oven with dangerous consequences. This can take place in a microwave

since the heating is relatively uniform throughout the liquid. With a stovetop, heating is via conduction from the burner or coil and there will be ample opportunity for small bubbles to form on the bottom long before the entire volume has reached the boiling point.

Most metal objects should be excluded from a microwave oven as any sharp edges (areas of high electric field gradient) may create sparking or arcing which at the very least is a fire hazard. Microwave safe metal shelves will have nicely rounded corners.

A microwave oven should never be operated without anything inside as the microwave generator then has no load - all the energy bounces around inside an a great deal is reflected back to the source. This may cause expensive damage to the magnetron and other components.

1.1 Construction of microwave oven

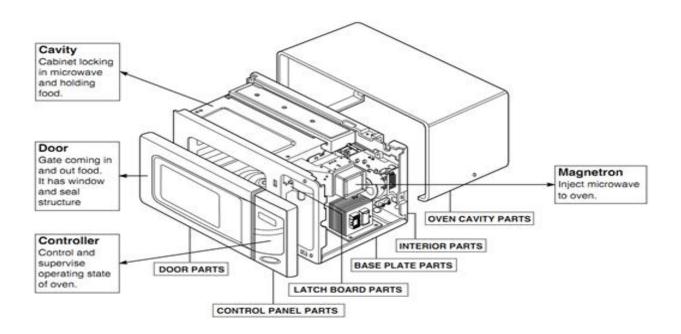


Figure (1.1)

1.1.1 Cavity

All cavity magnetrons consist of a hot cathode with a high (continuous or pulsed) negative potential created by a high-voltage, direct-current power supply. The cathode is built into the center of an evacuated, lobed, circular chamber. A magnetic field parallel to the filament is imposed by a permanent magnet. The magnetic field causes the electrons, attracted to the (relatively) positive outer part of the chamber, to spiral outward in a circular path, a consequence of the Lorentz force. Spaced around the rim of the chamber are cylindrical cavities. The cavities are open along their length and connect the common cavity space. As electrons sweep past these openings, they induce a resonant, high-frequency radio field in the cavity, which in turn causes the electrons to bunch into groups. (This principle of cavity resonator is very similar to blowing a stream of air across the open top of a glass pop bottle.) A portion of the field is extracted with a short antenna that is connected to a waveguide (a metal tube usually of rectangular cross section). The waveguide directs the extracted RF energy to the load, which may be a cooking chamber in a microwave oven or a high-gain antenna in the case of radar.

A cross-sectional diagram of a resonant cavity magnetron. Magnetic lines of force are parallel to the geometric axis of this structure.

The sizes of the cavities determine the resonant frequency, and thereby the frequency of emitted microwaves. However, the frequency is not precisely controllable. The operating frequency varies with changes in load impedance, with changes in the supply current, and with the temperature of the tube. This is not a problem in uses such as heating, or in some forms of radar where the receiver can be synchronized with an imprecise magnetron frequency. Where precise frequencies are needed, other devices such as the klystron are used.

The magnetron is a self-oscillating device requiring no external elements other than a power supply. A well-defined threshold anode voltage must be applied before oscillation will build up; this voltage is a function of the dimensions of the resonant cavity, and the applied magnetic field. In pulsed applications there is a delay of several cycles before the oscillator achieves full peak power, and the build-up of anode voltage must be coordinated with the build-up of oscillator output.

Where there are an even number of cavities, two concentric rings can connect alternate cavity walls to prevent inefficient modes of oscillation. This is called Pi strapping because the two straps lock the phase difference between adjacent cavities at Pi radians (180°).

The magnetron is a fairly efficient device. In a microwave oven, for instance, a 1.1 kilowatt input will generally create about 700 watts of microwave power, an efficiency of around 65%. (The high-voltage and the properties of the cathode determine the power of a magnetron.) Large S band magnetrons can produce up to 2.5 megawatts peak power with an average power of 3.75 kW. Large magnetrons can be water cooled. The magnetron remains in widespread use in roles which require high power, but where precise frequency control is unimportant

1.1.2 Door

The door of a microwave oven is carefully designed to reflect microwaves so that they can't escape from the oven. That mesh that you see in the door isn't plastic, it's metal. Metal surfaces reflect microwaves and, even though the mesh has holes in it to allow you to observe the food, it acts as a perfect mirror for the microwaves. Basically, the holes are so much smaller than the 12.2-cm wavelength of the 2.45-GHz microwave that the microwave cannot propagate through the holes. Electric currents flow through the metal mesh as the microwave hits it and those currents re-radiate the microwave in the reflected direction. Since the holes aren't big enough to disrupt that current flow, the mesh reflects the microwaves as effectively as a solid metal surface would.

After plugging your oven into a standard housing socket, press start button or turn the timer. And then switches (primary, secondary, timer) close the circuit..

Eventually the input power will be applied to turntable motor timer motor, fan motor, oven lamp a high voltage transformer.

A high voltage of 2100 volts AC is generated in the second winging of H.V transformer. And the voltage is doubled by H.V Capacitor & H.V Diode. The 4Kv DC voltage is applied to filament of magnetron, then magnetron start to produce microwave.

This microwave is injected to cavity.

1.1.3 Cooling fans

Since 30 to 50 percent of the power into a microwave oven is dissipated as heat in the Magnetron, cooling is extremely important. Always inspect the cooling fan/motor for dust and dirt and lubricate if necessary. A couple of drops of electric motor oil or 3-in-One will go a long way. If there are any belts, inspect for deterioration and replace if necessary.

An oven that shuts off after a few minutes of operation could have a cooling problem, a defective over temperature thermostat, a bad magnetron, or is being operated from very high AC line voltage increasing power to the oven.

One interesting note: Since 30 to 50 percent of the power goes out the vents in the back as heat, a microwave oven is really only more efficient than conventional means such as a stovetop or gas or electric oven for heating small quantities of anything. With a normal oven or stovetop, wasted energy goes into heating the pot or oven, the air, and so on. However, this is relatively independent of the quantity of food and may be considered to be a fixed overhead. Therefore, there is a crossover point beyond which it is more efficient to use conventional heat than high tech microwaves.

1.2 Controller

The controller usually includes a microcomputer, though very inexpensive units may simply have a mechanical timer (which ironically, is probably more expensive to manufacture!). The controller runs the digital clock and cook timer; sets microwave power levels; runs the display; and in high performance ovens, monitors the moisture or temperature sensors.

Power level in most microwave ovens is set by pulse width control of the microwave generator usually with a cycle that lasts 10-30 seconds. For example, HIGH will be continuous on, MEDIUM may be 10 seconds on, 10 seconds off, and LOW may be 5 seconds on, 15 seconds off. The power ratios are not quite linear as there is a 1 to 3 second warm up period after microwave power is switched on.

However, some models use finer control, even to the point of a continuous range of power. These are typically "inverter" models which use a more sophisticated type of power supply than the simple high voltage transformer, capacitor, rectifier, system described below. However, there have been some back in the 1970s that did this with a 1 second or so pulse width modulated cycle, fast enough to have the same effect as continuous control for all practical purposes.

The operating voltages for the controller usually are derived from a step down transformer. The controller activates the microwave generating circuitry using either a relay or triac.

1.3 Sensors

More sophisticated ovens may include various sensors. Most common are probes for temperature and moisture. A convection oven will include a temperature sensor above the oven chamber.

Since these sensors are exposed to the food or its vapors, failures of the sensor probes themselves are common.

1.4 How a microwave oven works?

The operation of a microwave oven is really very simple. It consists of two parts: the controller and the microwave generator.

The controller is what times the cooking by turning the microwave energy on and off. Power level is determined by the ratio of on time to off time in a 10-30 second cycle.

The microwave generator takes AC line power. Steps it up to a high voltage, and applies this to a special type of vacuum tube called a magnetron - little changed from its invention during World War II (for Radar).

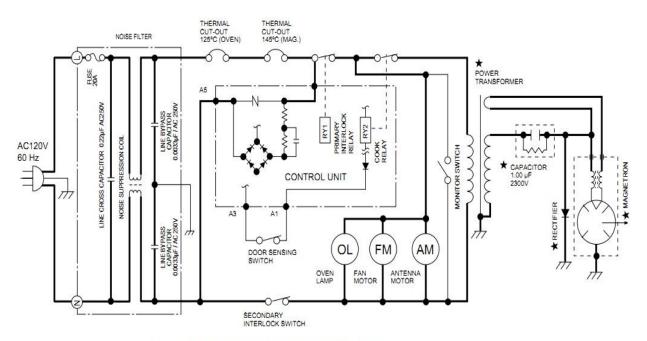


Figure O-2. Oven Schematic-Cooking Condition

Figure (1.2)

1.5 Microwave generator

This is the subsystem that converts AC line power into microwave energy. The majority of microwave ovens use a brute force approach which consists of 5 parts: high voltage (HV) transformer running off the AC line, HV rectifier diode, HV capacitor, magnetron, and waveguide to oven chamber. (A few employ solid state inverter in place of the simple HV transformer. These will be discussed later.)

The most common microwave generator consists of the following:

• High Voltage Transformer. Typically has a secondary of around 2,000 VRMS at 0.5 to 1 amp - more or less depending on the power rating of the oven. There will also be a low voltage winding for the Magnetron filament (3.3 V at 10 A is typical).

You cannot miss this as it is the largest and heaviest component visible once the cover is removed. There will be a pair of quick-connect terminals for the AC input, a pair of leads for the Magnetron filament. And a single connection for the HV output. The HV return will be fastened directly to the transformer frame and thus the chassis.

These transformers are designed with as little copper as possible. The primary for 115 VAC is typically only 120 turns of thick wire - thus about 1 turn per volt input and output (this is about 1/4th as many turns as in a "normal" power transformer. (It's usually

possible to count the primary turns by examining how it is wound - no disassembly required!) So there would be about 3 turns for the magnetron filament and 2080 turns for the high voltage winding for the transformer mentioned above. The reason they can get away with so few turns is that it operates fully loaded about 90 percent of the time but is still on the hairy edge of core saturation. The HV components are actually matched to the HV transformer characteristics. Performance will suffer if the uF value of a replacement HV capacitor is not close to that of the original.

There is also generally a "magnetic shunt" in the core of the transformer. This provides some current limiting, possibly to compensate for various magnetron load conditions. However, it's not enough to provide any reduction in the likelihood of electrocution should you come in contact with the HV winding!

- Rectifier usually rated 12,000 to 15,000 PRV at around 0.5 amp. Most commonly, this will be rectangular or cylindrical, about 0.5 inch long with wire leads. Sometimes, it is a box bolted to the chassis. One end will be electrically connected to the chassis.
- Capacitor 0.65 to 1.2 uF at a working voltage of around 2,000 VAC. Note that this use of 'working voltage' may be deceiving as the actual voltage on the capacitor may exceed this value during operation. The capacitor is metal cased with quick-connect terminals on top (one end). Always discharge the capacitor as described below before touching anything inside once the cover is removed.
- Magnetron the microwave producing tube includes a heated filament cathode, multiple resonant cavities with a pair of permanent ceramic ring magnets to force the electron beams into helical orbits, and output antenna. The magnetron is most often box shaped with cooling fins in its midsection, the filament/HV connections on the bottom section, and the antenna (hidden by the waveguide) on top. Sometimes, it is cylindrical in shape but this is less common. The frequency of the microwaves is usually 2.45 GHz.

When salvaging parts from dead microwave ovens, save the HV components (transformer, capacitor, and diode) as a group (assuming all are still good). Then, if a repair is needed to another oven it may be better to replace all 3 both because this eliminates uncertainty if more than 1 part failed or is marginal, and they will have been designed to have the best compatibility.

1.6 High voltage transformer

The transformer goes by several names, depending on where you are. Variable reluctance, leakage flux, stray flux, etc. It is exactly the same construction and operating principle as a neon transformer, some kinds of HID light ballasts and some series streetlight constant current

transformers.

The core is an almost standard "E" core (or "H" core if you prefer) with one exception. The center leg has an air gap. The windings are on the end legs of the "E" instead of the center leg.

There are two magnetic paths around the core for the field set up by the primary to travel. Around the periphery and across the secondary and around the center leg and across the air gap. The field that travels along the center leg does not cross the secondary and induces no voltage.

With no load applied, the bulk of the field travels the peripheral, very much lower reluctance solid iron path, inducing full secondary voltage proportional to the turns ratio. As current flows in the secondary, counter-MMF raises the reluctance of the peripheral path so that some of the flux travels through the center leg. With less flux traveling around the periphery and cutting across the secondary, the secondary voltage drops as the current remains about the same. At the 0++limit, if the secondary is shorted, the peripheral path has so much reluctance that most of the flux travels the center leg and across the air gap. The same current as before flows through the secondary but at zero volts.

When the dimensions of the core and gap are set up correctly, the transformer behaves as an almost perfect constant current device. That is, the secondary voltage varies as necessary to keep the same current flowing through a varying load. Just what the doctor ordered to keep the magnetron happy.

The secondary current can be increased by opening up the air gap. This raises the reluctance of that path and forces more field through the secondary leg. Closing the gap has the opposite effect.

The center leg is often called the magnetic shunt and frequently it is a separate piece of laminated iron stuck between the coils and TIG welded in place. It is a common trick for Tesla Coilers to open up a neon transformer and either knock out the shunt entirely or grind it down to open the air gap. This modification causes the transformer to output much more current than it is designed for - for a little while, at least, The same thing works with microwave oven transformers (MOT).

This design in a microwave oven is a vital part of keeping the magnetron anode current within spec. The magnetron is electrically a diode. A diode that isn't emission-limited would draw destructive current if not externally limited. With this design, the filament can be heated good and hot for long life and not have the tube run away. The design also is vital for protecting the magnetron from potentially damaging conditions such as operating the oven empty, arcing, etc.

It's popular to use several MOTs to build an arc welder. This works quite well specifically because these transformers are constant-current devices - exactly the characteristic stick welding needs. If they were conventional transformers, the first time the rod touched the work and shorted the secondary, fault current would flow and the breaker would trip or blue smoke would leak out.

Along similar lines, one can cut off the high voltage secondary and replace it with a suitable number of turns of heavy wire, connect a bridge rectifier and have a nice constant current battery charger. Select the turns carefully and it'll do the bulk/absorption stages of the smart 3 stage charging algorithm.

1.7 Magnetron

1.7.1 Magnetron construction and operation

The cavity magnetron was invented by the British before World War II. It is considered by many to be the invention most critical to the Allied victory in Europe.

The story goes that shortly after the War, a researcher at the Raytheon Corporation, Dr. Percy Spencer, was standing near one of the high power radar units and noticed that a candy bar in his shirt pocket had softened. In the typical 'I have to know why this happened' mentality of a true scientist, he decided to investigate further. The Amana Radarange and the entire future microwave oven industry were the result.

1.7.2 Magnetron construction

This is the description you will find in any textbook on radar or microwave engineering. The original Amana Radarange and other early microwave ovens likely used this design as well.

- 1. A centrally located cylindrical electron emitting cathode. This is supplied with pulsed or continuous power of many thousands of volts (negative with respect to the anode.
- 2. A cylindrical anode block surrounding but separate and well insulated from the cathode.
- 3. Multiple cylindrical resonator cavities at a fixed radius from the cathode bored in the anode block. Channels link the cavities to the central area in which the cathode is located.

The wavelength of the microwave energy is approximately 7.94 times the diameter of the cavities. (For the frequency of 2.45 GHz (12.4 cm) used in a microwave oven this would result in a cavity diameter of approximately .62" (15.7 mm).

- 4. An antenna pickup in one of the cylindrical cavities which couples the microwave energy to the waveguide.
- 5. The entire assembly is placed in a powerful magnetic field (several thousand Gauss compared to the Earth's magnetic field of about .5 Gauss). This is usually supplied by a permanent magnet though electromagnets have been also used. The original designs used huge somewhat horseshoe shaped permanent magnets which were among the most powerful of the day.
- 6. Cooling of the anode block must be provided by forced air, water, or oil since the microwave generation process is only about 60 to 75 percent efficient and these are often high power tubes (many kilowatts).

1.7.3 Magnetron construction - modern microwave oven

This description is specifically for the 2M214 (which I disassembled) or similar types used in the majority of medium-to-high power units. However, nearly all other magnetrons used in modern domestic microwave ovens should be very similar.

The item numbers are referenced to the diagram in the section: Cross section diagram of typical magnetron.

This is a view looking up through the anode cylinder from the filament end of the tube. See the text below for parts names and dimensions.

1. The filament and cathode are one in the same and made of solid tungsten wire, about .020" (.5 mm) diameter, formed in a helix with about 8 to 12 turns, 5/32" (4 mm) diameter and just over 3/8" (9.5 mm) in length. The cathode is coated with a material which is good for electron emission.

Note: this coating is the only material contained in the microwave oven magnetron that might be at all hazardous. Beryllium, a toxic metal, may be used in the form of a ceramic of beryllium oxide (BeO) in large radar magnetrons due to its excellent heat conductivity. But should not be present in modern domestic microwave ovens. However, see the section: SAFETY.

The filament gets its power via a pair of high current RF chokes - a dozen or so turns of heavy wire on a ferrite core - to prevent microwave leakage back into the filament circuit and electronics bay of the oven. Typical filament power is 3.3 VAC at 10 A.

The cathode is supplied with a pulsating negative voltage with a peak value of up to 5,000 V.

2. The anode is a cylinder made from .062" (1.5 mm) thick copper with an inside diameter of 1-3/8" (35 mm) and a length of about 1" (25.4 mm).

Steel plates (which probably help to shape the magnetic field, see below) and thin steel covers (to which the filament and antenna insulators are sealed) are welded to the ends of the cylinder.

The filament leads/supports enter through a cylindrical ceramic insulator sealed to the bottom cover and then pass through a hole in the bottom end plate.

3. Rather than cylindrical cavities (as you would find in most descriptions of radar magnetrons), there are a set of 10 copper vanes .062" (1.5 mm) thick and approximately 1/2" (12.7 mm) long by 3/8" (9.5 mm) wide. These are brazed or silver soldered to the inside wall of the cylinder facing inward leaving a 5/16" (8 mm) central area clear for the filament/cathode.

Surrounding this space are the .062" (1.5 mm) thick edges of the 10 vanes with gaps of approximately .04" (1 mm) between them.

Copper shorting rings at both ends near the center join alternating vanes. Thus, all the even numbered vanes are shorted to each other and all the odd numbered vanes are shorted to each other. Of course, all the rings are also all shorted at the outside where they are joined to the inner wall of the cylinder.

This structure results in multiple resonant cavities which behave like sets of very high quality low loss L-C tuned circuits with a sharp peak at 2.45 GHz. At this high frequency, individual inductors and capacitors are not used. The inductance and capacitance are provided by the precise configuration and spacing of the copper vanes, shorting rings, and anode cylinder.

- 4. A connection is made near the middle of a single vane to act as the output power takeoff. It passes through a hole in the top end plate, exits the tube via a cylindrical ceramic insulator sealed to the top cover, and attaches to the pressed-on bullnose antenna cap.
- 5. The entire assembly is placed in a powerful magnetic field (several thousand Gauss compared to the Earth's magnetic field of about .5 Gauss). This is provided by a pair of ceramic ring magnets placed against the top and bottom covers of the anode cylinder. For the 2M214, these are about 2-1/8" (54 mm) OD, 1-13/16" (46 mm) ID, 1/2" (12.7 mm) thick.
- 6. A set of thin aluminum fins act as a heat sink for removing the significant amount of wasted heat produced by the microwave generation process since it is only about 60 to 75 percent efficient. These are press fit on the magnetron anode and also in contact with the magnetron case. There will always be a cooling fan to blow air through this assembly.

The anode and magnetron case are at ground potential and connected to the chassis.

1.7.4 Magnetron construction - common features

The following items apply to all types of magnetrons.

- 7. The gap between the cathode and anode, and the resonant cavities, are all in a vacuum.
- 8. When powered, electrons stream from the cathode to the anode. The magnetic field forces them to travel in curved paths in bunches like the spokes of a wheel. The simplest way to describe what happens is that the electron bunches brush against the openings of the resonating cavities in the anode and excite microwave production in a way analogous to what happens when you blow across the top of a Coke bottle or through a whistle.

9. The frequency/wavelength of the microwaves is mostly determined by the size and shape of the resonating cavities - not by the magnetic field as is popularly thought. However, the strength of the magnetic field does affect the threshold voltage (the minimum anode voltage required for the magnetron to generate any microwaves), power output, and efficiency.

WARNING: What this implies is that if the magnetron is not present or is not drawing power for some reason - like an open filament - up to V (peak) will still be present across the capacitor when power is removed. At the end of normal operation, some of this will likely be discharged immediately but will not likely go below about 2,000 V due to the load since the magnetron does not conduct at low voltages.

Other types of power supplies have been used in a few models - including high frequency inverters - but it is hard to beat the simplicity, low cost, and reliability of the half wave doubler configuration. See the section: High frequency inverter type HV power supplies.

There is also usually a bleeder resistor as part of the capacitor, not shown. However: do not assume that this is sufficient to discharge the capacitor - always do this if you need to touch anything in the microwave generator after the oven has been powered. The bleeder may be defective and open as this does not effect operation of oven and/or the time constant may be long - minutes. Some ovens may not have a bleeder at all.

In addition, there will likely be an over-temperature thermostat - thermal protector - somewhere in the primary circuit, often bolted to the magnetron case. There may also be a thermal fuse or other protector physically elsewhere but in series with the primary to the high voltage transformer.

Other parts of the switched primary circuit include the oven interlock switches, cooling fan, turntable motor (if any), oven light, etc.

1.8 Interlock switches

Various door interlock switches prevent inadvertent generation of microwaves unless the door is closed completely. At least one of these will be directly in series with the transformer primary so that a short in the relay or triac cannot accidentally turn on the microwaves with the door open. The interlocks must be activated in the correct sequence when the door is closed or opened.

Interestingly, another interlock is set up to directly short the power line if it is activated in an incorrect sequence. The interlocks are designed so that if the door is correctly aligned, they will sequence correctly. Otherwise, a short will be put across the power line causing the fuse to blow forcing the oven to be serviced. This makes it more difficult for an ignorant consumer to just bypass the door interlocks should they fail or to run the oven with an open door as a room heater - and protects the manufacturer from lawsuits. (That interlock may be known as a "dummy

switch" for obvious reasons and is often not even mentioned in the schematic/parts manifest.) Of course, should that switch ever actually be used, not only will the fuse blow, but the switch

contacts will likely be damaged by the high initial current! This also means it probably wouldn't be a bad idea to replace the interlock switch which might have been affected if your oven fails with a blown fuse due to a door problem.

Failed door interlocks account for the majority of microwave oven problems - perhaps as high as 75 percent. This is not surprising considering that two of the three switches carry the full oven current - any deterioration of the contacts results in increased resistance leading to their heating and further deterioration. And, opening the door to interrupt a cook cycle results in arcing at the contacts. Complete meltdowns are not unusual! If any defective door switches are found, it is probably a good idea to replace all of them as long as the oven is already apart.

The typical door switches and their function:

- **Door Sensing**: Input to the microcontroller to indicate the state of the door.
- **Interlock Monitor**: Shorts out the AC line (and blows the main fuse) should the Primary Interlock not open due to incorrect sequencing of the door switches or a failed switch.
- **Primary Interlock**: In series with the high voltage (magnetron) power supply so cuts power when the door is open.

Note that if the Door Sensing switch should malfunction, peculiar behavior may occur (like the fan or turntable operating at the wrong time) but should never result in microwaves being generated with the door open.

1.9 Objective

Controller unit is an important part of the each system, to design a universal controller for microwave oven we need to program accordingly either using assembly or C languages. The following **chapter is based on assembly programming using MPLAB**.

Chapter2

Assembly Language

2.1 Introduction

This is a brief introduction to assembly language. Assembly language is the most basic programming language available for any processor. With assembly language, a programmer works only with operations implemented directly on the physical CPU. Assembly language lacks high-level conveniences such as variables and functions, and it is not portable between various families of processors. Nevertheless, assembly language is the most powerful computer programming language available, and it gives programmers the insight required to write effective code in high-level languages. Learning assembly language is well worth the time and effort of every serious programmer.

2.1.1 The Basics

Before we can explore the process of writing computer programs, we have to go back to the basics and learn exactly what a computer is and how it works. Every computer, no matter how simple or complex, has at its heart exactly two things: a CPU and some memory. Together, these two things are what make it possible for your computer to run programs.

On the most basic level, a computer program is nothing more than a collection of numbers stored in memory. Different numbers tell the CPU to do different things. The CPU reads the numbers one at a time, decodes them, and does what the numbers say. For example, if the CPU reads the number 64 as part of a program, it will add 1 to the number stored in a special location called AX. If the CPU reads the number 146, it will swap the number stored in AX with the number stored in another location called BX. By combining many simple operations such these into a program, a programmer can make the computer perform many incredible things.

As an example, here are the numbers of a simple computer program: 184, 0, 184, 142, 216, 198, 6, 158, 15, 36, 205, and 32. If you were to enter these numbers into your computer's memory and run them under MS-DOS, you would see a dollar sign placed in the lower right hand corner of your screen, since that is what these numbers tell the computer to do.

2.1.2 Assembly Language

Although the numbers of the above program make perfect sense to a computer, they are about as clear as mud to a human. Who would have guessed that they put a dollar sign on the screen? Clearly, entering numbers by hand is a lousy way to write a program.

It doesn't have to be this way, though. A long time ago, someone came up with the idea that computer programs could be written using words instead of numbers. A special program called an *assembler* would then take the programmer's words and convert them to numbers that the computer could understand. This new method, called writing a program in *assembly language*, saved programmers thousands of hours, since they no longer had to look up hard-to-remember numbers in the backs of programming books, but could use simple words instead.

The program above, written in assembly language, looks like this:

MOV AX, 47104 MOV DS, AX MOV [3998], 36 INT 32

When an assembler reads this sample program, it converts each line of code into one CPU-level instruction. This program uses two types of instructions, MOV and INT. On Intel processors, the MOV instruction moves data around, while the INT instruction transfers processor control to the device drivers or operating system.

The program still isn't quite clear, but it is much easier to understand than it was before. The first instruction, MOV AX, 47104, tells the computer to copy the number 47104 into the location AX. The next instruction, MOV DS, AX, tells the computer to copy the number in AX into the location DS. The next instruction, MOV [3998], 36 tells the computer to put the number 36 into memory location 3998. Finally, INT 32 exits the program by returning to the operating system.

Before we go on, I would like to explain just how this program works. Inside the CPU are a number of locations, called registers, which can store a number. Some registers, such as AX, are general purpose, and don't do anything special. Other registers, such as DS, control the way the CPU works. DS just happens to be a *segment register*, and is used to pick which area of memory the CPU can write to. In our program, we put the number 47104 into DS, which tells the CPU to access the memory on the video card. The next thing our program does is to put the number 36 into location 3998 of the video card's memory. Since 36 is the code for the dollar sign, and 3998 is the memory location of the bottom right hand corner of the screen, a dollar sign shows up on the screen a few microseconds later. Finally, our program and execute another in its place. In our case, we want interrupt 32, which ends our program and goes back to MS-DOS, or whatever other program was used to start our program.

2.1.3 Running the Program

Let's go ahead and run this program. First, be sure to print these instructions out, since you will need to refer to them as we go on. Next, click on your start menu, and run the program called MS-DOS Prompt. A black screen with white text should appear. We are now in MS-DOS, the way computers used to be 20 years ago. MS-DOS was before the days of the mouse, so you

must type commands on the keyboard to make the computer do things.

First, I want you to type the word debug, and press enter. The cursor should move down a line, and you should see the Debug prompt, which is a simple dash. We are now in a program called *Debug*. Debug is a powerful utility that lets you directly access the registers and memory of your computer for various purposes. In our case, we want to enter our program into memory and run it, so we'll use Debug's a command, for *assemble*. Go ahead and type a100 now. The cursor will move down another line, and you will see something like 1073:0100. This is the memory location we are going to enter assembly language instructions at. The first number is the segment, and the second number is the memory location within the segment. Your Debug program will probably pick a different segment for your program than mine did, so don't worry if it's different. Another thing to note is that Debug only understands hexadecimal numbers, which are a sort of computer shorthand. Hexadecimal numbers sometimes contain letters as well as well as digits, so if you see something like 63AF, don't worry.

Let's go ahead and enter our program now. Type each of the instructions below into Debug exactly as they appear, and press enter after each one. When you finish entering the last instruction, press enter twice to tell Debug that we are done entering instructions.

mov ax,B800
mov ds,ax
mov byte[0F9E],24
int 20

As you can see, I've converted all the numbers into hexadecimal, and have made a few other changes so Debug can understand what's going on. If you make a mistake while entering the above program, press enter twice, type a100, and start entering instructions again at the beginning of the program.

Once you have entered the program, you can go ahead and run it. Simply type g for *go* and press enter when you are ready to start the program. You should see a dollar sign in the lower right hand corner of your screen and the words Program terminated normally. These words are put out by Debug to let you know that the program ended normally. Congratulations! You've just entered and run your first assembly language program!

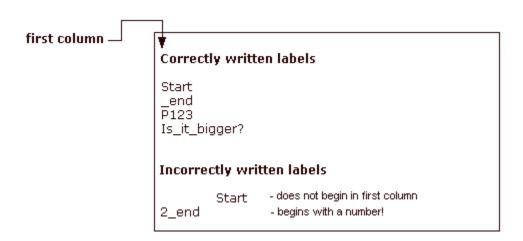
2.2 Assembly language elements

Basic elements of assembly language are:

- Labels
- Instructions
- Operands
- Directives
- Comments

2.2.1 Labels

A **Label** is a textual designation (generally an easy-to-read word) for a line in a program, or section of a program where the micro can jump to - or even the beginning of set of lines of a program. It can also be used to execute program branching (such as Goto) and the program can even have a condition that must be met for the Goto instruction to be executed. It is important for a label to start with a letter of the alphabet or with an underline "_". The length of the label can be up to 32 characters. It is also important that a label starts in the first column.



2.2.2 Instructions

Instructions are already defined by the use of a specific microcontroller, so it only remains for us to follow the instructions for their use in assembly language. The way we write an instruction is also called instruction "syntax". In the following example, we can recognize a mistake in writing because instructions movilp and gotto do not exist for the PIC16F84 microcontroller.

Correctly written instructions

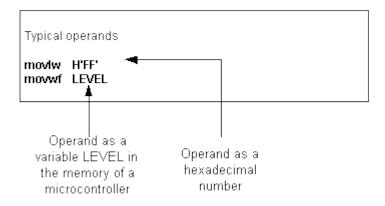
movlw	H'01FF'
goto	Start

Incorrectly written instructions

movlp	H'01FF'
gotto	Start

2.2.3 Operand

Operand is the instruction elements for the instruction are being executed. They are usually **registers** or **variables** or **constants**.



2.2.4 Comments

Comment is a series of words that a programmer writes to make the program more clear and legible. It is placed after an instruction, and must start with a semicolon ";".

2.2.5 Directives

A **directive** is similar to an instruction, but unlike an instruction it is independent on the microcontroller model, and represents a characteristic of the assembly language itself. Directives are usually given purposeful meanings via variables or registers. For example, LEVEL can be a designation for a variable in RAM memory at address 0Dh. In this way, the variable at that address can be accessed via LEVEL designation. This is far easier for a programmer to understand than for him to try to remember address 0Dh contains information about LEVEL.

Some frequently used directives: PROCESSOR 16F84 #include "p16f84.inc" __CONFIG _CP_OFF & _WDT_OFF & _PWRTE_ON & _XT_OSC

2.3 Basic program is MPLAB

There are a few things you need in every program. Might as well get them in the file now.

When entering data in the MPLAB assembler, there are three columns of interest. The columns are separated by whitespace (tabs and space). How much whitespace is entirely up to us? We can use a single space, or 10 tabs, really doesn't matter to the assembler. Personally, I like to use two tabs. This makes the column line up without thinking much about it, and it allows a reasonable length for identifiers.

The first column is anything that starts in column 1. The assembler assumes that this is a label that we will reference somewhere in our program.

The second column contains the opcode. This is the thing we want the PIC to do dome thing to.

Besides instructions, there can be assembler directives. These don't end up as instructions in the PIC, instead, they tell the assembler things we want it to know.

We need three directives in any program:

LIST	P=16F877A
#INCLUDE	<p16f877a.inc></p16f877a.inc>

END

It's also a good idea to include the configuration word. We will talk about this one in more detail, but for now, type in the following:

<tab><tab>processor<16f876A> <tab><tab>include<tab><tab><16f876A.inc><enter> <tab><tab>__config<tab>_HS_OSC & _WDT_OFF & _PWRTE_ON <enter> <tab><tab>end<enter> The processor directive tells the assembler which type of PIC we are using. The include directive tells the assembler to include a file which contains definitions for a number of symbols relevant to that processor. The __config tells the processor that we will be using a crystal (_HS_OSC),

we want the watchdog timer turned off (_WDT_OFF) and we want the power-up timer enabled (_PWRTE_ON).

Select 'file->save' to save your work, than select to build all

'Project->Bulk All'

We will get a new window with a bunch of junk, but the last line should say:

BUILD SUCCEEDED

2.4 Addressing modes

RAM memory locations can be accessed directly or indirectly.

2.4.1 Direct Addressing

Direct Addressing is done through a 9-bit address. This address is obtained by connecting 7th bit of direct address of an instruction with two bits (RP1, RP0) from STATUS register as is shown on the following picture. Any access to SFR registers is an example of direct addressing.

1.			
2.			
3.	Bsf	STATUS, RPØ	;Bankl
4.	movlw	ØxFF	;w=0xFF
5.	movwf	TRISA	;address of TRISA register is taken from
6.			;instruction movwf

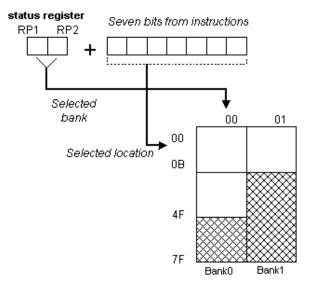


Figure (2.1)

2.4.2 Indirect Addressing

Indirect unlike direct addressing does not take an address from an instruction but derives it from IRP bit of STATUS and FSR registers. Addressed location is accessed via INDF register which in fact holds the address indicated by a FSR. In other words, any instruction which uses INDF as its register in reality accesses data indicated by a FSR register. Let's say, for instance, that one general purpose register (GPR) at address 0Fh contains a value of 20. By writing a value of 0Fh in FSR register we will get a register indicator at address 0Fh, and by reading from INDF register, we will get a value of 20, which means that we have read from the first register its value without accessing it directly (but via FSR and INDF). It appears that this type of addressing does not have any advantages over direct addressing, but certain needs do exist during programming which solved smoothly through indirect addressing. can be only

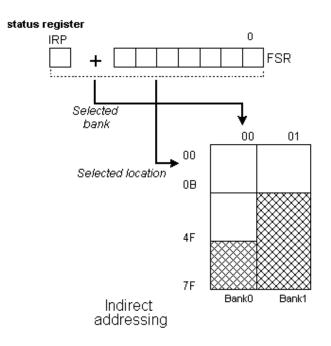


Figure (2.2)

Such examples include sending a set of data via serial communication, working with buffers and indicators (which will be discussed further in a chapter with examples), or erasing a part of RAM memory (16 locations) as in the following instance.

	Movlw OxOC	; initialization
	Movwf FSR	;FSR indicates address OxOC
LOOP	clrf INDF	; INDF = O
	incf FSR	;address = initial address + 1
	btfss FSR,4	are all locations erased;
	goto loop	;no, loop again
CONTI	NUE:	

Reading data from INDF register when the contents of FSR register is equal to zero returns the value of zero, and writing to it results in NOP operation (no operation).

2.5 Writing to EEPROM Memory

In order to write data to EEPROM location, programmer must first write address to EEADR register and data to EEDATA register. Only then is it useful to set WR bit which sets the whole action in motion. WR bit will be reset, and EEIF bit set following a writing what may be used in processing interrupts. Values 55h and AAh are the first and the second key whose disallow for accidental writing to EEPROM to occur. These two values are written to EECON2 which serves only that purpose, to receive these two values and thus prevent any accidental writing to EEPROM memory. Program lines marked as 1, 2, 3, and 4 must be executed in that order in even time intervals. Therefore, it is very important to turn off interrupts which could change the timing needed for executing instructions. After writing, interrupts can be enabled again.

Example of the could	part of a progra look	m which writes data 0x something	EE to first loca like	ntion in EEPRC the	M memory following:
bcf STATUS, movlw OxOO		bankO,EEADR at O9h addresswritten to			
movwf EEADR		address being trans EEADR	ferred to		
movlw OxEE	;	write the value Ox1	EΕ		
movwf EEDATA	;	data goes to EEDAT.	A register		
bsf STATUS, 1	RPO ;	Bank1 EEADR at 09h			
bof INTCON,	GIE ;	all interrupts dis	abled		
bsf EECON1,	WREN ;	writing enabled			
movlw 55h					
movwf EECON2	;	first key 55htoEEC	ON2		
movlw AAh					
movwf EECON2	;	second key AAhto E	ECON2		
bsf EECON1,W	R ;	initialize writing			
bsf INTCON,	GIE ;	interrupt enabled			

NOTE: It is recommended that WREN be turned off the whole time except when writing data to EEPROM, so that possibility of accidental writing would be minimal. All writing to EEPROM will automatically clear a location prior to writing a new.

2.6 Cblock

If you recall, in earlier lessons, we allocated locations in the file register for our

Various memory needs, and we assigned names to their locations with equ

statements. There's nothing wrong with this. But the cblock directive has a

number of advantages.

The sequence

Cblock	H'20'
Spot1	; First program variable
Spot2	; Second program variable
endc	

Is exactly the same as

Spot1 equ H'20'; First program variable Spot2 equ H'21'; Second program variable

But has the advantage that the assembler keeps track of adding one each time we use another location. Obviously, this isn't a big win for only 2 locations. But as our programs get longer, it's a bigger help.

There's another reason we want to use this construct for allocating file register memory. If we later decide we want to use a different PIC model, this can save us some work in modifying the code for the new processor. For example, the PIC16F84A has file register memory starting at H'0C'. If we run out of program memory and decide to move to a PIC16F628, we have more program memory as well as file register memory, but the file register starts at H'20'. We may have dozens of lines to edit if we used the equ form, and plenty of opportunity for errors. With the cblock, we have only one directive to change.

We will continue to use equ to define manifest constants, and this convention has the additional advantage of making our memory allocation definitions stand out from constant declarations.

2.7 The code

To do a subtraction, we want to initially set the C bit, so it is available to borrow from. Before all done, set up the following code:

; set up a subtraction movlw H'03' bsf STATUS,C subwf Spot2,F movlw H'0f'

subwf Spot2,F

2.8 Looping

There is another pair of increment/decrement instructions. They are incfsz and decfsz (increment F and skip if zero, likewise for decrement). Try this (again, before alldone):

; Lets do a counter

clrf Spot1

loop

incfsz Spot1,F goto loop

Now, when we run this, watch what happens to the file register location Spot1. Notice that the first time the incfsz is executed, the file register gets bumped up to one. Two more clicks of the Step Into button and it becomes two. Now select Debugger->Animate and watch the file register. The program runs freely, but the screen is updated after each instruction so we can watch the file

register location increment. When it wraps around to zero, the program leaves the loop (because the incfsz instruction finally skipped the goto) and reaches our alldone loop.

The incfsz instruction changes none of the status bits, but it does take action (skipping the next instruction) when the result is zero.

2.9 SETS OF INSTRUCTION

The RISC Stands for "Reduced Instruction Set Computing, "and is pronounced "risk." It is arguably the fastest and most efficient microprocessor technology available today. The RISC architecture is an improvement upon the CISC (Complex Instruction Set Computing) architecture used in the original Intel Pentium chips. In 1974, John Cocked of IBM Research was working on making a faster version of the CISC chip and came up with a design that significantly reduced the number of instructions need for performing computations. The new design was not only faster than the CISC architecture, but the chips were also smaller and less expensive to manufacture. Motorola's PowerPC chips (such as the G4 in Power Macs) are the most widely used RISC-based chips. Intel has slowly been integrating RISC technology into its chips, but they still are mostly CISC-based.

ADDLW K

- o Add the literal value K to register WREG and put the result back in the WREG register
- $\circ \quad (\mathbf{W}) + \mathbf{k} \rightarrow (\mathbf{W})$
- K is an 8-bit value: 0-255 (decimal), 00-FF (hex)
- L: literal (actual value)

Affect STATUS bits: C, DC, Z

Instruction: ADDLW 15

Before	After
W=10	W=25

ADDWF f, d

- Add together contents of WREG and a file register location (SFR @ GPR).
- \circ Put the result in the register WREG if d = 0 otherwise it is stored back in register f.
- $\circ \quad (\mathbf{W}) + (\mathbf{f}) \to (\mathbf{d})$
- $0 \le f \le 127, d \in [0, 1]$
- Affect STATUS bits: C, DC, Z

Instruction:	MOVLW	17H
	ADDWF	5H,0

Before	After
W=0H	W=17H
5H=0H	5H=0H

MOVF f, d

- o Move the content of f register upon the status of d
- \circ (f) \longrightarrow (d)
- Affect bit'Z' of Status register
- Instruction: MOVF FSR, 0

Before	After
W=09AH	W=value in FSR register
FSR=0H	Z=1

ANDLW k

- Logical AND k literal with the content of WREG register & the result is placed in the WREG register
- $\circ \quad (W) \text{ AND } k \rightarrow (W)$
- Affect Z bit of STATUS register

Instruction: ANDLW 5FH

Before	After
W=A3H	W=03H

ANDWF f, d

- o AND the WREG register with f register
- $\circ \quad (W) + (f) \rightarrow (d)$
- Affect Z bit of STATUS register

Instruction: ANDWF FSR, 1

Before	After
W=17H	W=17H
FSR=0C2H	FSR=02H

BCF f, b

- Clear bit 'b' in file register
- $\circ \quad 0 \rightarrow (f < b >)$
- Not affect on STATUS register

Instruction: BCF STATUS, 5

Before	After
STATUS=0A7H	STATUS=087H

BSF f, b

- Set bit 'b' in f register
- \circ 1 \rightarrow (f)
- Not affect on STATUS register

Instruction: BSF INTCON, 7

Before	After
INTCON=0BH	INTCON=08BH

BTFSS f, b

- $\circ~$ Execute the next instruction if bit 'b' in file register 'f' is '0', otherwise discard executing next instruction
- 2-cycle instruction
- Not affect on STATUS register

Instruction: H BTFSS STATUS, 2

I GOTO LOOP

J

•••••

Before	After
PC=address H	PC=Add.j if STATUS<2>=1,
	PC=Add.I if STATUS<2>=0

BTFSC f, b

- Execute the next instruction if bit 'b' in file register 'f' is '1', otherwise discard executing next instruction
- o 2-cycle instruction
- Not affect on STATUS register

Instruction: H BTFSC PORTA, 3

I GOTO LOOP

J

•••••

Before	After
INTCON=0BH	INTCON=08BH

CALL k

- o Call subroutine
- \circ (PC) + 1 \rightarrow TOS (top of stack)
- \circ k \rightarrow PC<10:0>
- \circ (PCLATCH<4:3>) \rightarrow PC<12:11>
- o 2-cycle instruction

• Not affect on STATUS register

Instruction: SO CALL THEN

•••••

•••••

Before	After
PC=add.SO	PC=ADD.THEN;
	TOS=add.SO+1

CLRF f

- Clear the content of 'f' register
- $\circ \quad 00h \to (f)$
- $\circ 1 \rightarrow Z$

Instruction: CLRF PORTA

Before	After
PORTA=5AH	PORTA=00H
	Z=1

CLRW

- Clear the content WREG register
- $\circ \quad 00h \to (W)$
- $\circ 1 \rightarrow Z$

Instruction: CLRW

- $\circ \quad \mbox{Clear the content WREG register}$
- $\circ 00h \rightarrow (W)$
- \circ 1 \rightarrow Z

Instruction: CLRW

Before	After	
W=5AH	W=00H	
	Z=1	

COMP f, d

- Complement the content of 'f' register
- $\circ \quad (f) \to (d)$

Instruction: COMPONE, 0

Before	After
ONE=13H	ONE=13H
W=02H	W=0ECH

DECF f, d

• Decrease 'f' register

 $\circ \quad (f) - 1 \rightarrow (d)$

Instruction: DECF CNT, 1

Before	After
CNT=01H	CNT=00H
Z=0	Z=1

DECFSZ f, d

- Decrease 'f' register and skip the next instruction if the result is 0; otherwise execute the next instruction
- \circ (f) 1 \rightarrow (d), skip if result = 0
- 2-cycle instruction

Instruction: HERE DECFSZ CNT, 1

GOTO HERE

CONT

Before	After
PC=add.HERE	CNT=CNT-1
	PC=add.CONT if CNT =0;
	PC= add.HERE+1 if CNT≠0

GOTO k

- Unconditional branch
- \circ k \rightarrow PC<10:0>
- $\circ \quad (\text{PCLATCH}{<}4{:}3{>}) \rightarrow \text{PC}{<}12{:}11{>}$
- 2-cycle instruction

Instruction: HERE GOTO THERE

•••••

THERE

Before	After
PC.add.	PC=add.THERE
HERE	

INCF f, d

• Increase the content of 'f' register

 $\circ \quad (f) + 1 \rightarrow (d)$

 \circ d is destination

Instruction: INCF SATU, 1

Before	After
SATU	SATU=00H
	Z=1

INCFSZ f, d

- Increase the content of 'f' register and skip the next instruction if the result is 0; otherwise execute the next instruction
- \circ (f) + 1 \rightarrow (d), skip if result = 0
- 2-cycle instruction

Instruction: HERE INCFSZ CNT, 1

GOTO loop

CONT

•••••

Before	After
PC=add.HERE	CNT=CNT+1
	PC=add.CONT if CNT=0;
	Else add.HERE

IORLW k

- Inclusive OR literal 'k' with the content of WREG register
- $\circ \quad (W) \text{ OR } k \rightarrow (W)$
- Affect bit 'Z' of STATUS register

Instruction: IORLW 35H

Before	After
W=09AH	W=0BFH
Z=?	Z=0

IORWF f, d

- Inclusive OR the content of WREG register with f register
- $\circ \quad (W) \text{ OR } (f) \rightarrow (d)$
- Affect bit 'Z' of STATUS register

Instruction: IORWF RESULT, 0

Before	After
RESULT=13H	RESULT=13H
W=91H	W=93H
	Z=0

NOP

 \circ No operation

Instruction: NOP

RETFIE

- Return from interrupt
- $\circ \quad \text{TOS} \to \text{PC}$
- \circ 1 \rightarrow GIE (Global Interrupt Enable)
- Not affect bit of STATUS register

Instruction: RETFIE

Before	After
	PC=TOS, GTE=1

RETLW k

- Return with loading literal 'k' onto WREG register, $k \rightarrow (W)$
- $\circ \quad \text{TOS} \to \text{PC}$
- Not affect on STATUS register

Instruction: RETLW 088H

Before	After
W=09AH	W=088H

RETURN

- Return from subroutine
- $\circ~$ POP the TOS and load into the PC
- 2-cycle instruction

Instruction: RETURN

Before	After
	PC=TOS

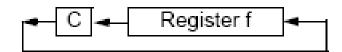


Figure (2.3)

- Rotate left f through carry
 Affect bit 'C' of STATUS register

Instruction: RLF REG, 1

Before	After
REG=1111 1111=0FFH	REG=1111 1110=0FEH
C=0	C=1

RRF f, d

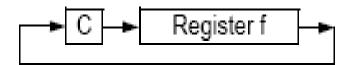


Figure (2.4)

- Rotate right f through carry
 Affect bit 'C' of STATUS register

Instruction: RRFREG, 1

Before	After
REG=1111 0111 =0F7H	REG=0111 1011 =07BH
C=0	
	C=1

SLEEP

- $\circ \quad 00h \rightarrow WDT$
- $\circ 0 \rightarrow WDT \text{ pre-scalar}$
- $\circ \quad 1 \to TO$
- $\circ \quad 0 \to PD$
- o Affect TO & PD bits of STATUS register

Instruction: SLEEP

SUBLW k

- Subtract WREG register (2's complement) from literal 'k' and put the result onto WREG register
- $\circ \quad k (W) \to (W)$
- Affect C, DC & Z bits of STATUS register

Instruction: SUBLW 02H

Before	After
W=01H	W=01H
C=?	C=1
Z=?	Z=0

SUBWF f, d

- Subtract WREG register (2's complement) from f register
- $\circ \quad (f) (W) \to (d)$
- Affect C, DC & Z bits of STATUS register

Instruction: SUBWF 02H, 0

Before	After
W=01H	W=04H
F=05H	F=05H
C=?	C=1
Z=?	Z=0
Z=:	Δ=0

SWAPF f, d

- Exchange the upper & lower nibbles off register
- $(f<3:0) \rightarrow (d<7:4>), (f<7:4) \rightarrow (d<3:0>)$
- Not affect STATUS register

Instruction: SWAPF ON, 1

Before	After
ON=0F4H	ON=04FH
W=09AH	W=09AH

XORLW k

- Exclusive OR (XOR) the content of WREG register with k literal
- $\circ \quad (W) \text{ XOR } k \rightarrow (W)$
- Store the result in WREG register
- Affect bit 'Z' of STATUS register

Instruction: XORLW 0AFH

Before	After
W=0B5H	W=01AH

XORWF f, d

- Exclusive OR (XOR) the content of WREG register with f register
- $\circ \quad (W) \text{ XOR } (f) \rightarrow (d)$
- Affect bit 'Z' of STATUS register

Instruction: XORWF REG, 1

Before	After
REG=0AFH	REG=01AH
W=0B5H	W=0B5H

These instructions can help us to write code in assembly language (MPLAB) for PIC microcontrollers. Where design a universal controller we need to use PIC 16F876A microcontroller as a main part of control unit.

The following chapter is based on controller design for microwave oven.

Chapter 3

CONTROLLER DESIGN

3.1 Introduction

The heart of the each system is control system, the control system means a system the operation of the another system or control systems, combination of components (electrical, mechanical, thermal or hydraulic) that act to gather to maintain actual system performance close to desired set of performance.

Now a days technologies are advance so in place of relay or circuit breaker mostly using microcontroller to control the operation of a system.

Our objective in this chapter is to design a control unit that can control the operation of oven with keypad, trough out the chapter we will get some idea of main unit (microcontroller, LCD, voltage regulator, and temperature sensor).

In the next chapter we will go through operation by IR Receiver (Remote control)

3.2 PIC16f876A/PIC18f252

The PIC16F876A/PIC18f252 is the latest products from *Microchip*. It features all the components which modern microcontrollers normally have. For its low price, wide range of application, high quality and easy availability, it is an ideal solution in applications such as: the control of different processes in industry, machine control devices, measurement of different values etc. Some of its main features are listed below.

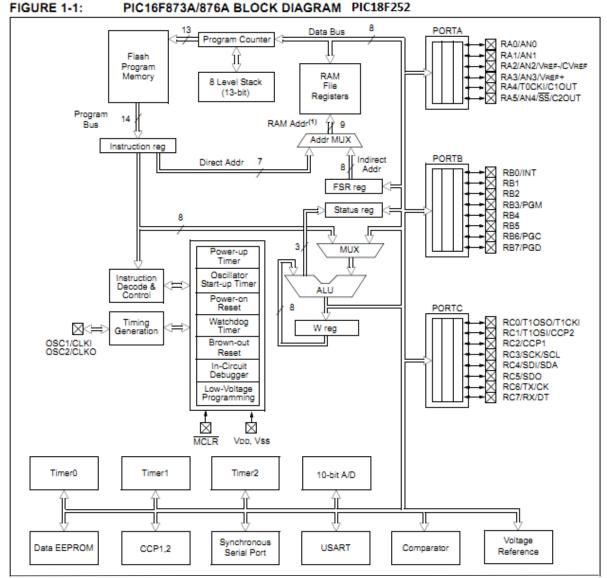


Figure (3.1)

40

Key features	PIC 16f876A	PIC 18f252	
Operating frequency	DC-20MHz	DC-40MHz	
Resets (and delays)	POR,BOR(PWRT, OST)	POR, BOR , RESET INSTRUCTIONS,	
		STACK FULL(PWRT)OST	
Flash program memory (14-	8K	32K	
bit words)			
Data memory(bytes)	368	1536	
EEPROM data memory	256	256	
(bytes)			
Interrupts	15	17	
I/O ports	PIN (A,B,C,D,E)	PIN(A,B,C,D,E)	
Timers	3	4	
Capture/ compare/pwm	2	2	
modules			
Serial communications	MSSP, USART	MSSP, ADDRESSABLE USART	
Parallel communication	PSP	PSP	
10-bit analog-to- digital	8 INPUT CHANNELS	8 INPUT CHANNELS	
modules			
Analog comparators	2	-	
instruction set	35	75	
Packages	40-PIN PIDP	28-PIN DIP	
	44-PIN PLCC	28-PIN SOCC	
	44-PIN TQFP		
	44-PIN QFN		

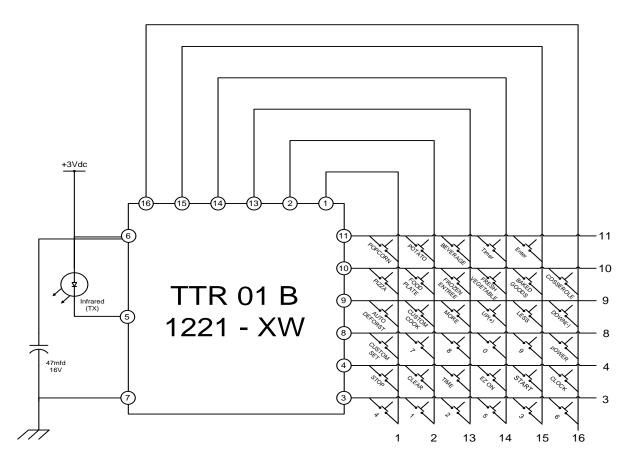


Figure (3.2)

We have got in here 35 keys which make it possible to do different functions by keypad, this is attached to the microwave oven and by pressing the key we can get the appropriate operation.

- 1. DISPLAY WINDOW.
- 2. ONE TOUCH CONTROL: This menu has been preprogrammed to cook food automatically by one touch.
- 3. AUTO DEFROST: This feature provides you with the best defrosting method for frozen foods.
- 4. CUSTOM COOK: This feature allows you to set and execute a frequently used single stage program.
- 5. NUMBER: These used to set for time of day, cooking time, power level, or defrost weight.
- 6. MORE / LESS: All pf the one touch cook and TIMED COOK can be adjusted to cook food for a longer or shorter time.

MORE ———— pressing MORE will add 10 seconds to the cooking time. LESS _____ pressing LESS will subtract 10 seconds of cooking time.

STOP/ CLEAR: it used to stop oven and clear all entries except time of day.

- 8. CUSTOM SET: You can select sound on/off, clock on/off, scroll speed, lbs/kg choice, language choice, demo on / off mode.
- 9. TIME: You can set the desired cooking time.
- 10. POWER: You can select the desired power level for cooking.
- 11. TIMER: You can use the timer function of your oven for purpose other than coking.
- 12. CLOCK: It is used to set the time of day.
- 13. EZ ON: You can extend cooking time in multiplies of 1 minute by repeatedly touching this pad during cooking.
- 14. START: This feature allows oven to begin functioning.

By pressing any key a signal is going to microcontroller which cases the operation microwave oven through magnetron.

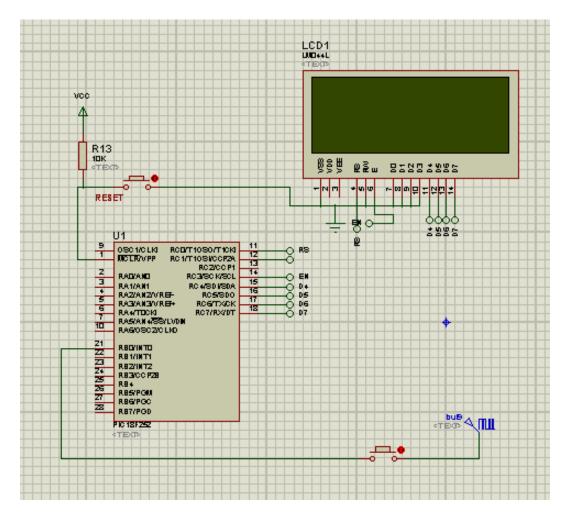


Figure (3.3)

The above a part of the controller circuit is given which shows the microcontroller with LCD for keypad operation of microwave oven .

3.3 TEMPERATURE SENSOR (DS1820)

The DS1820 Digital Thermometer provides 9-bit temperature readings which indicate the temperature of the device.

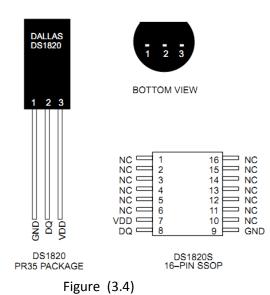
Information is sent to/from the DS1820 over a 1–Wire interface, so that only one wire (and ground) needs to be connected from a central microprocessor to a DS1820.

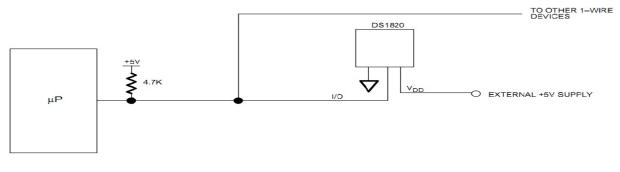
Power for reading, writing, and performing temperature conversions can be derived from the data line itself with no need for an external power source.

Because each DS1820 contains a unique silicon serial number, multiple DS1820s can exist on the same 1–Wire bus. This allows for placing temperature sensors in many different places. Applications where this feature is useful include HVAC environmental controls, sensing temperatures inside buildings, equipment or machinery, and in process monitoring and control.

Pin 16-pin SSOP	Pin PR35	SYMBOLS	Description
9	1	GND	Ground
8	2	DQ	Data input/output pin
			for 1-wire: open drain
7	3	VDD	Optional VDD pin

Using VDD to supply temperature conversion current





Figure(3.5)

3.3.1 Operation – Measuring Temperature

The DS1820 measures temperature through the use of an on-board proprietary temperature measurement technique.

The DS1820 measures temperature by counting the number of clock cycles that an oscillator with a low temperature coefficient goes through during a gate period determined by a high temperature coefficient oscillator.

The counter is preset with a base count that corresponds to -55° C. If the counter reaches zero before the gate period is over, the temperature register, which is also preset to the -55° C value, is incremented, indicating that the temperature is higher than -55° C.

At the same time, the counter is then preset with a value determined by the slope accumulator circuitry. This circuitry is needed to compensate for the parabolic behavior of the oscillators over temperature. The counter is then clocked again until it reaches zero. If the gate period is still not finished, then this process repeats. The slope accumulator is used to compensate for the non-linear behavior of the oscillators over temperature, yielding a high resolution temperature measurement.

This is done by changing the number of counts necessary for the counter to go through for each incremental degree in temperature. To obtain the desired resolution, therefore, both the value of the counter and the number of counts per degree C (the value of the slope accumulator) at a given temperature must be known. Internally, this calculation is done inside the DS1820 to provide 0.5° C resolution. The temperature reading is provided in a 16–bit, sign–extended two's complement reading. Table 1 describes the exact relationship of output data to measured temperature. The data is transmitted serially over the 1–Wire interface. The DS1820 can measure temperature over the range of -55° C to $+125^{\circ}$ C in 0.5° C increments. For Fahrenheit usage, a lookup table or conversion factor must be used.

Note that temperature is represented in the DS1820 in terms of a $1/2^{\circ}$ C LSB, yielding the following 9-bit format:

MSB				LSB				
1	1	1	0	0	1	1	1	0

 $= -25^{\circ}C$

The most significant (sign) bit is duplicated into all of the bits in the upper MSB of the two-byte temperature register in memory. This "sign-extension" yields the 16-bit temperature readings as shown in Table 1.

Higher resolutions may be obtained by the following procedure. First, read the temperature, and truncate the 0.5°C bit (the LSB) from the read value. This value is TEMP_READ. The value left in the counter may then be read. This value is the count remaining (COUNT_REMAIN) after the gate period has ceased.

The last value needed is the number of counts per degree C (COUNT_PER_C) at that temperature. The actual temperature may be then be calculated by the user using the following:

 $TEMPERATURE = TEMP_READ - 0.25 + \frac{(COUNT_PER_C_COUNT_REMAIN)}{COUNT_PER_C}$

TEMPERATURE	DIGITAL OUTPUT	DIGITAL OUTPUT
	(binary)	(Hex)
+125°C	0000000 11111010	00FA
+25°C	0000000 00110010	0032h
+1/2°C	0000000 00000001	0001h
+0°C	0000000 0000000	0000h
-1/2°C	11111111 11111111	FFFFh
-25°C	1111111111001110	FFCEh
-55°C	11111111 10010010	FF92h

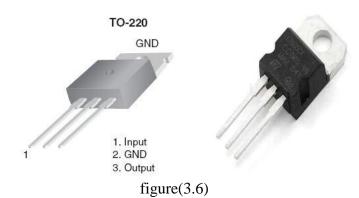
TEMPERATURE/DATA RELATIONSHIPS Table (3.1)

3.4 Voltage Regulator (LM7805)

The MC7805 of three terminal positive regulator are available in the TO-220/D-PAK package and with several fixed

output voltages, making them useful in a wide range of applications. Each type employs internal

current limiting, thermal shut down and safe



operating area protection, making it essentially indestructible. If adequate heat sinking is provided, they can deliver over 1A output current. Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltages and currents.

Absolute maximum Ratings

Parameter	Symbol	Value	Unit
input Voltage (for VO = 5V to 18V)	VI	35	V
(for VO = 24V)	VI	40	V
Thermal Resistance Junction-Cases (TO-220)	RØJC	5	°C/W
Thermal Resistance Junction-Air (TO-220)	RθJA	65	°C/W
Operating Temperature Range	TOPR	0~+125	°C
Storage Temperature Range	TSTG	-65 ~ +150	°C

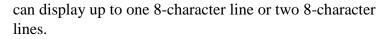
Electrical Characteristics (MC7805/LM7805)

(Refer to test circuit ,0°C < TJ < 125°C, IO = 500mA, VI = 10V, CI= 0.33μ F, CO= 0.1μ F, unless otherwise specified)

Parameter	Symbol	Condition	MC	unit				
				Min.	Туре	Max.		
Output Voltage	Vo	TJ =+25 c	рС	4.8	5.0	5.2	V	
		5.0mA ≤ Io ≤ 1.0A, I	PO ≤ 15W	4.75	5.0	5.25		
		VI = 7V to 2	20V					
Line Regulation	Regline	TJ=+25 oC	VO = 7V to	-	4.0	100		
(Note1)			25V				mV	
			VI = 8V to	-	1.6	50		
			12V					
		TJ=+25 oC	0 = 5.0mA	-	9	100		
	Regload		to1.5A				mV	
Load			0 =250mA	-	4	50		
Regulation			to					
(Note1)			750mA					

3.5 LCD HD-44780

The HD44780U dot-matrix liquid crystal display controller and driver LSI displays alphanumeric, Japanese kana characters, and symbols. It can be configured to drive a dot-matrix liquid crystal display under the control of a 4- or 8-bit microprocessor. Since all the functions such as display RAM, character generator, and liquid crystal driver, required for driving a dot-matrix liquid crystal display are internally provided on one chip, a minimal system can be interfaced with this controller/driver. A single HD44780U



The HD44780U has pin function compatibility with the HD44780S which allows the user to easily replace an LCD-II with an HD44780U. The HD44780U character generator ROM is extended to generate 208 5 \times 8 dot character fonts and 32 5 \times 10 dot character fonts for a total of 240 different character fonts. The low power

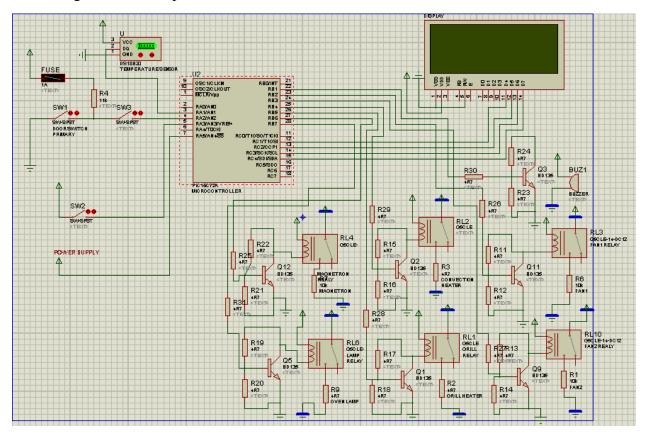
supply (2.7V to 5.5V) of the HD44780U is suitable for any portable battery-driven product requiring low power dissipation.



figure (3.7)



figure (3.8)



Block diagram with Temperature sensor is shown below

Figure (3.9)

The above show a part of the microwave oven circuit which consist of microcontroller, LCD, temperature sensor, number of relays.

In the next chapter I am going to talk about IR Receiver (Remote control) design for operation of microwave oven

Chapter 4

IR (Infrared) Receiver

IR receiver is one of the latest technologies where we are using it to control the operation of TV, Multimedia etc. IR stands for Infra-Red, and IR are part of the light spectrum beyond human eyesight capability. So far we know that there are many different types of light spectrum around any object in the world, physically, chemically, and among all these lights spectrum some of them are visible and some of them are invisible and X-Ray. We will see how IR acts in light spectrum in terms of frame timing later on.

The mediums in the wireless communication are many, but the two most popular mediums in the wireless communication are:

- 1- Infrared (IR)
- 2- Radio Frequency (RF).

Later models have incorporated the IR receiver as an integral part of the laptop. Most modern models no longer uses IR as this has been replace by the Bluetooth technology and then WiFi (wireless networking). There are some laptop models that have all 3.

IR technologies are better suited for short distance, low-to-medium data throughput, and wireless communication channels,

IR receiver has defined the standard as a wireless communication link between two devices in which the information is transmitted using infrared light.

Where to control the operation of microwave oven by IR receiver is a new idea that developed by our group.

4.1 IR data communication protocol

Communication is one of the great fundamental factors of today's technologies in the world, it plays an important role in the industries and as well as in day-to-day of human's life, and has direct effect in today's technologies. Communication is dealing to a condition to provide facilities and the way of interaction between humans and different technologies in the world.

So far we know that, technologies have been developing, we can see a huge differences in today's technologies and the ones as it was at the beginning, many change has became in the size, model, and effectiveness of usage in different areas and so on.

So, in order to use the new technologies effectively and to have a resized model, proper direction and communication with technologies we have tried to replace the microwave oven's

keypad with IR remote for parallel operations.

There are two most important standard electronics devices in terms of communications, these two are:

- 1- IR transmitters and
- 2- IR receivers.

In the main time IR transmitters and IR receivers are based on different types, models and different companies.

Initially, Sony Infrared Receiver PCVA-IR6U would be as it implies; it is an add-on device to a laptop/computer to enable said laptop/computer to be able to receive IR (infrared) signals from external sources such as a cell phone, another laptop or any other electronic product that has a built-in IR transmitter.

4.2 IR transmitters

IR Transmitter is a breakout for a simple and clear infrared LED on it. These Infrared LED operates around 940nm and work well for generic IR systems including remote control and touch-less object sensing. Pair them with any of our IR receivers



Figure (4.1)

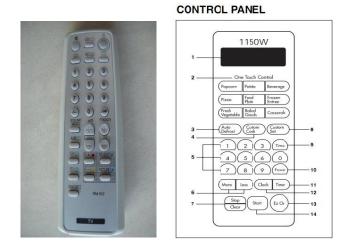


Figure (4.2)

figure (4.3)

4.3 IR receivers

IR receiver is a breakout board with IR detector mounting on it.IR detector is little microchips with a photocell that are tuned to listen to infrared light at 38KHz. They are almost always used for remote control detection – every TV and DVD player has one of these in the front to listen for the IR signal from the clicker.



Figure (4.4)

4.4 Frame timing

In order to communicate or we can say to receive IR or infrared signals form a certain sources for this case we have used IR TOSP1738

Command and Address bits are encoded as a 600us "low" pulse followed by:

• 600us "high" pulse for a logical bit zero

1200us "high" pulse for a logical bit onePlease note that the output ("low" and "high"levels) of a TSOP1738 is inverted in relation tothis picture.

This decoder is implemented as an "interrupt on change" service routine running on the pin where the TSOP1738 is connected. A hardware timer is used as a counter to measure the time between transitions, allowing the ISR to run for a very short time to manipulate the timer and change

its internal state, leaving immediately to the main loop.

Sony infrared remote protocol:

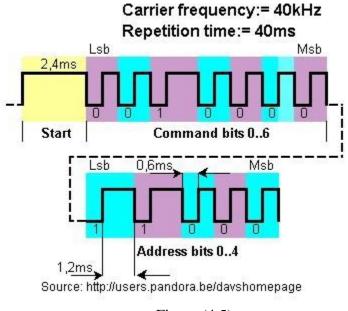
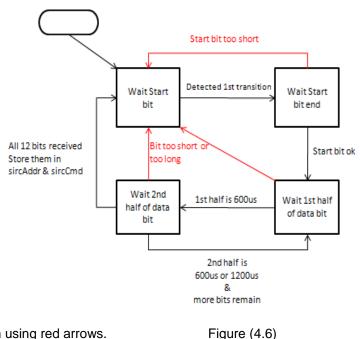


Figure (4.5)

Every time the TSOP1738 pin changes the ISR changes its internal state according to the next diagram:

In short, and after running several times for very short periods, once for every time the TSOP1738 pin flips, the SIRC ISR does the following: It waits for a start bit and when it finds one, it goes on to decode the Command and Address bits, by validating both halves of the bits. The first half of each data bit is always 600us long and the second half may be 600us is the bit is a logical 0 or 1200us if the bit is a logical 1. After decoding all 12 Command and Address bits, the decoder rests at the "Wait start bit" state.

Every time an error happens, because a bit length is out of the permitted values, the decoder aborts and goes to the "Wait start bit" state, where it waits for



the next frame. These errors are shown in the diagram using red arrows.

4.5 IR or Infrared Interface

The two most popular mediums in the wireless arena are Infrared (IR) and Radio Frequency (RF). IR technologies are better suited for short distance, low-to-medium data throughput, and wireless communication channels. Two common types of IR technologies are currently in use. These are:

- 1. TV Remote (TVR) and
- 2. IrDC (Infrared Data communication) standard protocol.

The IrDC (Infrared Data communication) has defined the standard as a wireless communication link between two devices in which the information is transmitted using infrared light.

The IrDC standard is a set of specifications for providing a universal two-way wireless infrared data communications, based on a practical cost, short-range point-to-point user model. The standard defines the physical characteristics of the interface, the communications protocols that provide for different needs, and the transmission speeds at which the infrared device communicates. 54

The two basics of the infrared communication standards are **IrDC-Data** and **IrDC-Control**. **IrDC-Data** defines the standard for the wireless, two-way infrared data transmission between two devices and consists of a set of mandatory protocols: IrPHY (Physical), IrLAP (Link Access), and IrLMP (Link Management).

IrDC-Control is the infrared standard that allows wireless peripherals such as keyboards, mouse, game pads, joysticks, and other pointing devices to interact with many types of host devices. Host devices include PCs, home appliances, game consoles, and TV/ audio devices/ Web set top boxes.

IrDC-Control is not the same as the standard TV Remote Control. IrDC-Control has its own set of mandatory protocols: PHY (Physical), MAC (Media Access Control), and LLC (Logical Link Control).

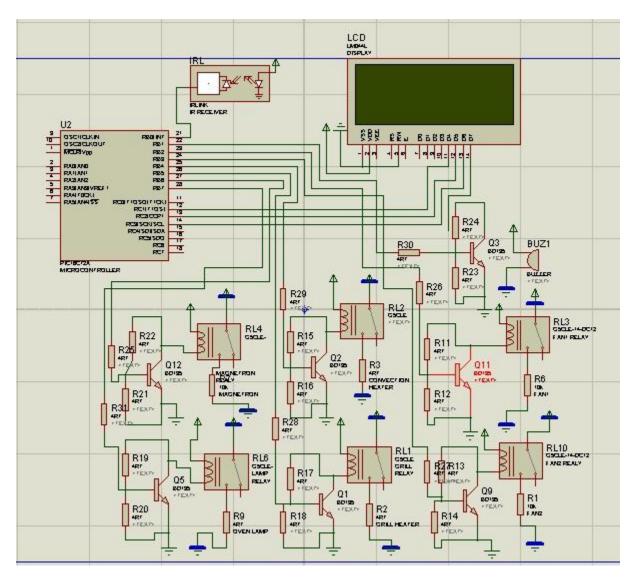
IrDA technology has emerged as one of the most promising wireless solutions because it offers several compelling advantages over other types of wireless communication interfaces.

Although infrared is only applicable between two devices at a time and cannot transmit through walls, the positive aspects of this technology are many.

Because infrared can only communicate from one device to another and because this communication must be line-of-sight, there is no risk that someone may intentionally or unintentionally obtain your information as it is being transferred.

IrDC infrared port module is the most mature of the wireless communications standards. These devices include cell phones, pagers, laptops, PDAs, digital cameras, handheld scanners, and laser printers. The IrDA standard has both support and user applications in all major operating systems including all recent versions of Windows, Windows CE, Linux, as well as the Palm operating systems.

Part of control diagram with IR Receiver





The c block diagram of the control unit of the microwave oven in which operate with IR Receiver. Where by pressing any key a signal is received by IR TOSP1738 from remote showing the condition in LCD display and magnetron start operation.

Chapter 5

Outcomes

As we thought through out the chapters now we are here to get the result of our work.

Where design of universal controller for microwave oven to satisfy the every one's need. Where everyone have a microwave oven in their homes. So by facing problems where the keypad not working or some other problems inside you don't need to through it out you can place this design as a control unit for your oven.

Complete block diagram

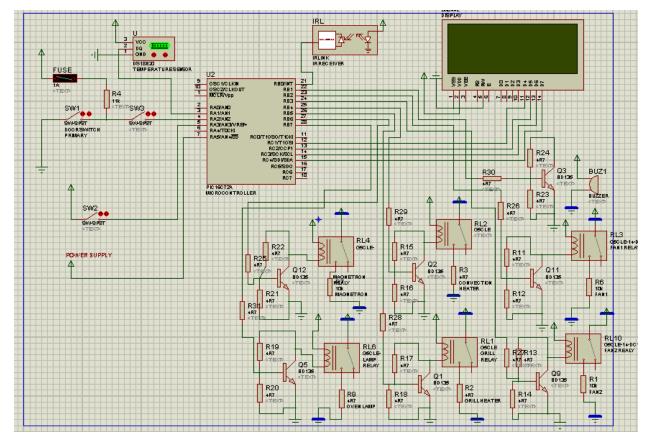


Figure (5.1)

5.1 Features

- Use of IR Receiver is a new idea for microwave oven. Where before never used this for microwave oven.
- Possibility to except both PIC 16 & PIC 18 microcontrollers.
 We can have large program which need more than 8k byte so for that we can use 32 k Byte as well.
- ➢ Use of temperature sensor instead of RTD.

- Standard protocol SIRC for IR Receiver.
- > Use of **Optocoupler** to handle large current
- ➤ Use of 2N-2222 (NPN)Transistor this can be used for back light of LCD.
- > A diode is used for safety purpose form high current

The result of out work is given below

5.2 Design snap- shot



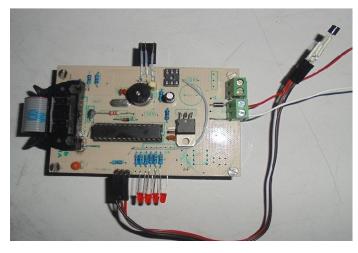


Figure (5.2)

Figure (5.3)



Figure (5.4)

Chapter 6

Conclusion

Finally we are coming across a research that we have done on our goals and project that have been expected from concept and ideas based on Microwave Oven controller design which this ideas and researches caused to control any kinds of functionalities or working principles that are used in a Microwave oven to lead its different applications and purposes.

In order to do this or to control the functionalities or working principles of microwave oven we use Microcontroller, which is a programmable device (PIC16F877A) used to be programmed and execute the instructions that have been given or programmed by programming language such as MPLAB which we have mentioned earlier in case of controller design in detailed form. As it is so, thus it is applicable for any kinds of Microwave oven and so we can design a universal keypad as well.

The study was set out to explore the concept of Microwave oven controller design and has identified the natures, forms, principle of operations, types of Microwave ovens, according to the reasons and diversification advantages, the type, the extent, resources required for diversification and the role and impact of intervention on the Microwave oven economy and well-being.

The study has also thought to know whether this design towards its diversification advantages can result in effective cost reduction or being cost effect, particularly within different kinds of Microwave oven.

In this aims the theoretical cases for diversification therefore needs to be revisited in order further understand the controller and designing dynamics of the designing a controller and how it can be made more sustainable.

The sustainable framework suggests the achievement of accumulation from diversification within the rural economy or being cost effect It is however, noted from this study that such a benefit is not likely for most rural microwave oven with the obvious alternative of survival being the more probable outcome of diversification.

The scale of our thesis and project is therefore extensive and multifaceted even at the local level.

To generate achievable policy, strategies and development targets with regards to diversification, being well outcome there is need for more case studies at the local level to allow further assessment of local dimensions of the subject. Exploring the following as future research Strategies can facilitate the attainment of this goal.

The study has offered an evaluative perspective on an important development due to our certain goal and the concepts of project, policy program, and was conducted by microcontroller for controlling the designing the Microwave oven and its application through sampling farm

Controller design and finally results in a universal keypad as well.

As a direct consequence of this methodology, the study encountered a number of limitations, which need to be considered.

In order to reach to achievable results and to have outcomes that are resulted from this study or our project and thesis and have been identified towards its different application, there were two or more important factors or standard topics were necessary to be discussed and needed to be considered as essential and major parts in overall the project they are such as assembly language microcontroller, IR receiver or Infra Red receiver and its data communication protocol and some other parameters that have been considered in this study which they are related to the ideas or our research that we have been dealing with it(Microwave oven controller design).

Each and every one of these topics has been discussed in detail specially the things which were important to our goal in order to lead us to our desired objectives with real and applicable outcomes.

In case of controller, in order to control the operation of microwave oven or its functionalities we have used microcontroller PIC16F877A / PIC16F876A, obviously we know that microcontroller have different type, size, forms and numbers, it varies according to its applications, functions, number of instructions and so on. Therefore we have used microcontroller PIC16F877A / PIC16F876A, because it matches to application of our project (microwave oven controller design universal keypad).

In this study we have discussed microcontroller in detail in the previous chapter.

In case of programming ,so far we know that microcontrollers are programmable device used to in programming to execute different instructions ,this instructions that have been given to the microcontroller by programmable language ,although there are different programmable languages like high level language such us java ,PHP , C , C++ and so on, we have used assembly language because it's easy to write different instructions easily ,in this issues assembly language has been instructed and written in MPLAB according to the characteristics of microcontroller which has different ports ,addresses ,memories and so on .

And finally basically the main focus was on the change (objective, goals resulted from our project the concept of microwave oven controller design) which have been developed in our project (the change or objective is to replace microwave ovens keypad and use remote controller instead of keypad), due to this issue the changes or objectives is towards the following advantages:

6.1 Advantages: Remote controller

1-cost effect (economy)2-tacking less space rather than microwave oven keypad3-ease of installation rather than microwave oven keypad

6.2 Disadvantages

1-for activation of microwave oven we have to take the remote controller exact and directly to the target.

Appendix

LIST P=PIC18F252, F=INHX32, C=160, R=DEC, X=ON #INCLUDE P18F252.INC CONFIG CONFIG1H, OSCS ON 1H & XT OSC 1H; EXTERNAL CLOCK ON OSC1 & OSC2 CONFIG CONFIG2H, WDT OFF 2H :WATCHDOG TIMER DISABLED. _CONFIG2L, _BOR_OFF_2L & _PWRT_ON_2L ; BROWN 2.0V, NO CONFIG POWER-UP TIMER __CONFIG _CONFIG3H, _CCP2MX_OFF_3H __CONFIG __CONFIG4L, _STVR_OFF_4L & _LVP_OFF_4L & _DEBUG_OFF_4L _CONFIG5L, _CP0_OFF_5L & _CP1_OFF_5L & _CP2_OFF_5L & CONFIG _CP3_OFF_5L ; ALL PROTECTION OFF 0.-302.-306.-307 ERRORLEVEL ; ;80 BYTES ON BANKO ACCESS ALLOWED DULY BANK SET BIT

CBLOCK 0X000 ; START OF RAM ADDRESSES USED IN PROGRAM

LCD_TMP LCD CHAR ; ADDR ; TOFFS FLAGS ; RS_VALUE ; DEL0 DEL1 DEL2 **INCHAR** DELAYCOUNTER_INNER DELAYCOUNTER_OUTER DELAYCOUNTER_FREQ COUNT1 COUNTA **COUNTB**

D D R(R R L_ H T T T T T T T T T T T T T T T T T T	1 2 _BYTE _BYTE EMP1 EMP2 EMP3	
S B F F F F F B C C C C C C C C C C C C C	REG_TEMP FATUS_TEMP SR_TEMP SR1H_TEMP SR1L_TEMP SR0H_TEMP SR0L_TEMP CD T_POINTER SB_RELD_ON IODE_FLAG MT_CODE MT_CODE MT_CMND MT_ADDR MT_ADDR MT_ADDR_N &_TIMER &_BIT_CNTR &_FLAGS XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	;to save WREG during interrupt ;to save STATUS during interrupt ;to save BSR during interrupt ;to save FSROH during interrupt ;to save FSROL during interrupt ;to save FSROL during interrupt ;to save FSROL during interrupt
ENDC ;************ DS_TRIS	******************** EQU	****** TRISB ;
DS_PORT	EQU	PORTB ;

DS_BIT	EQU	.0	;			
*****	*****	*****	******			
#DEFINE	Е	PORTC,3	• •			
#DEFINE	RS	PORT	С,0 ;			
#DEFINE	BEEP	PORTA,2	; DS 1820 A	ATTACHEI) HER	E
#DEFINE code of d .************************************	REMOTE	****	PORTB ,1		the	family
, CLK	=	.4	•			
SCRFLAFMASK =	B'11111100'	;				
;*************************************			===		=====	==LCD
SET_8B EQU 0X30	; SET	8 BIT DATA (FOR INITIA	LISATION	Ð	
SET_4B_1L EQU 0X SET_4B_2L EQU 0X DISP_ON EQU 0X0 CLR_DISP EQU 0X0 ENTRY_INC EQU 0X0	28 ; SET 4 B C ; DISPLAY 01 ; CLEAR I	IT DATA, 2 LI Y ON, CURSOI DISPLAY	NES R OFF, BLIN			
DD_RAM_ADDR EQU	0X80 ; LEA	AST SIGNIFIC.	ANT 7 BITS	ARE FOR	ADDF	RESS
;;====================================			===	IMANDS	· ↓ ↓ ↓ ↓ ↓ ↓	AND
·*************************************	* * * * * * * * * * * * * * * *	* * * * * * * * * * * * * * * * *	****	****	****	*****
START_CONV EQU	0X44	; SET 8 BIT I	DATA (FOR	INITIALIS	ATION	N)
COPY_SCRATCH EQU READ_SCRATCH EQU WRITE_SCRATCH EQU RECALL_PSUPPLY EQU RECALL_SCRATCH	0XBE ; SE 0X4E ; SE 0XB4 ; SE	T 4 BIT DATA T 4 BIT DATA T 4 BIT DATA T 4 BIT DATA 8 ; SET 4 BIT	, 1 LINES , 2 LINES , 1 LINES	NES		

ALARM_SEARCH READ_ROM MATCH_ROM	EQU 0XEC ; SET 4 BIT DATA, 1 LINES EQU 0X33 ; CLEAR DISPLAY EQU 0X55 ; ENTRY MODE INCREMENT, NO SHIFT
SKIP_ROM	EQU 0XCC ; LEAST SIGNIFICANT 7 BITS ARE FOR ADDRESS
SEARCH_ROM	EQU 0XF0 ; DISPLAY ON, CURSOR OFF, BLINK OFF
;XXXXXXXXXXXXX CONSTANT CONSTANT CONSTANT CONSTANT MODE ;XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	$IR_RD_ON = .1 ; FOR DIS BANK IN SOLID MODE$
CONSTANT	IR_REPEAT =.2; FOR DIS BANK IN SOLID MODENEW_BYTE =.3; FOR DIS BANK IN SOLID MODE
;XXXXXXXX PAUSE MACE	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX
MOVLW	(DLYF / 5) - 1;
MOVWF	TMP0 ;
CALL DLY5	N ;
ENDM	;
;====== ; MACRO FOF	R DS1820
, DQLOW MACH	RO ;
BCF	DS_PORT,DS_BIT ; DQ BIT READY
BCF	DS_TRIS,DS_BIT ; SET DQ TO OUTPUT

ENDM

;

;===== DQHIZ	===== Z	MACF	====== RO				;				=		
		BSF		DS_TR	IS,D	S_BIT	;	SET I	DQ TC) INPU	JT		
		ENDM	I			;							
;XXXX	XXXXX	XXXXX	XXXXX) MOVE XXXXX AL,DEST	XXX	XXXX	ХХХУ	XXXX	XXXX	XXXX	X		,
Μ		7 LITE 7 DEST	•	OF MAC	;PLA	ACE T	HE V	ALUI	e in d	ESTI		ION FII	; LE ;
;=====;	ORG (CLRF	======)X000		;START US		ECTOF		E AR	E AT I	BANI	= K 0		
; GOTO	CLRF XX) NOP GOTC	X) OP						D (BEFORE					
;=====		0X008 PULL_		;HIGH] ;HIGH]									
;==== ;XXXX PULL_	XXXXX _RAM	XXXXX		LOW F; XXXXX	XXX	XXXX	XXX	XXXX	XXXX	XXXX	X		
	MOVE			STATU				MP	;SAV			REGIS	
REGIS	MOVE STER MOVE			WREG, BSR,BS			EMP		;SAV	SA'; E BSF		GISTER	WORKING R
	MOVE	ŦF		FSR0H,	,FSR	ROH_T	EMP		;SAV	E FSR	ROH F	REGIST	ER
	MOVE	ŦF		FSR0L,	FSR	0L_TH	EMP		;SAV	E FSR	ROL R	EGIST	

	MOVFF	FSR1H,FSR1	H_TEMP	;SAVE FSR0H REGISTER	
	MOVFF	FSR1L,FSR1	L_TEMP	;SAVE FSR0L REGISTER	
;==== INT	BTFSC	INTCON,TM	======================================	======================================	
SER	GOTO	TIME_JUKAR		; IF YES GOTO TIME COUNTER	
,	GOTO XXXXXXXXX	INTCON3,IN UPDT_RMT_CODE POINT_RETURN XXXXXXXXXXXXX E TO COUNT TH	e xxxxxxxxx	XXXXXXXX IMER DEFINED BY THE USER	
INTE ; THE	RFAC E CLOCK FREQ		Z AND PRESC	CALER IS DEFINED FOR 1:2 F	
	LAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA	; CALLING LINE F			
GO	ΤΟ	POINT_RETURN	; RETURN F	ROM INTERRUPT	
;XXX	;*************************************				
·****	CALL ACQR_LO_T BTFSC IR_FLAGS,IR_ERROR GOTO ERR_RMT_CODE ;ERR_RMT_CODE :************************************				
VALI	DATE_START MOVLW SUBWF BTFSSSTAT GOTO INVA	.4 IR_TIMER,W US,C	;ERR_RMT_	CODE	
• • • • •	MOVLW SUBWF BTFSC GOTO INVAI	.5 IR_TIMER,W STATUS,C LID_START	;ERR_RMT_	CODE	

VALID_START CALL ACQR_HI_T IR FLAGS, IR ERROR BTFSC GOTO ERR_RMT_CODE ;ERR_RMT_CODE BSF **IR FLAGS, STRT PASS** CLRF RMT_CMND_N CLRF RMT ADDR N INIT_IR_CMD_READ **MOVLF** .7, IR_BIT_CNTR READ_CMND_BITS CALL ACOR LO T BTFSC IR_FLAGS, IR_ERROR GOTO ERR RMT CODE CALL ACQR_HI_T IR_FLAGS, IR_ERROR BTFSC GOTO ERR_RMT_CODE CMND_BIT_OK IR TIMER,W MOVF 0X02 ANDLW 0XFF ADDLW RRCF RMT CMND N,F DECFSZ IR_BIT_CNTR,F GOTO READ CMND BITS RRNCF RMT_CMND_N,F READ_IR_ADDR_BYTE MOVLF .5, IR BIT CNTR READ_ADDR_BITS ACQR_LO_T CALL BTFSC IR FLAGS, IR ERROR ERR_RMT_CODE GOTO MOVF IR_BIT_CNTR,W XORLW 0X01 BTFSC STATUS.Z JUMP HI TEST GOTO CALL ACQR_HI_T BTFSC IR FLAGS, IR ERROR GOTO ERR_RMT_CODE

JUMP_HI_TEST

MOVFIR_TIMER,W ANDLW 0X02 ADDLW 0XFF RRCF RMT_ADDR_N,F DECFSZ IR_BIT_CNTR,F READ_ADDR_BITS GOTO FOUND_FRESH_BYTE RRNCF RMT_ADDR_N,F RRNCF RMT_ADDR_N,F RRNCF RMT_ADDR_N,F RMT ADDR N,RMT ADDR MOVFF MOVFF RMT_CMND_N,RMT_CMND BSF IR FLAGS, NEW BYTE GOTO POINT RETURN INVALID_START BCF IR_FLAGS,STRT_PASS ERR_RMT_CODE BSF IR_FLAGS, IR_ERROR BCF IR FLAGS, NEW BYTE POINT RETURN **T1CON** CLRF BCF INTCON3,INT1IF **MOVFF** FSR1L TEMP, FSR1L ;RESTORE FSR0L REGISTER MOVFF FSR1H TEMP, FSR1H :RESTORE FSR0H REGISTER **MOVFF** :RESTORE FSR0L REGISTER FSR0L_TEMP,FSR0L **MOVFF** FSR0H_TEMP,FSR0H :RESTORE FSR0H REGISTER **:RESTORE BSR REGISTER** MOVFF BSR_TEMP,BSR WREG TEMP, WREG **MOVFF** :RESTORE WORKING REGISTER **MOVFF** STATUS TEMP, STATUS :RESTORE STATUS REGISTER RETFIE ENSURE WE ARE AT BANK 0

;XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX						
MAIN_PROG						
;XXX			XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX			
	CALL INIT_PORT ;INITIALIZING I/O PORTS CALL INIT_LCD ; INITIAL LCD					
	CALL INI	II_LCD ; INII	IAL LCD			
	CALL LC	D_CLR	· · · · · · · · · · · · · · · · · · ·			
;===== LCD_1	====== DIAGNOS7	=====================================				
;	CALL	LCD_CLR	;			
;	MOVLW	.5				
	CALL	LCD_LINE1				
	MOVLW	'W'				
	CALL	DATA2LCD				
	MOVLW	'E'				
	CALL	DATA2LCD				
	MOVLW	'L'				
	CALL	DATA2LCD				
	MOVLW	'C'				
	CALL	DATA2LCD				
	MOVLW					
	CALL MOVLW	DATA2LCD				
	CALL	'M' DATA2LCD				
	MOVLW	'E'				
	CALL	DATA2LCD				
•****	*****	*****	*****			
,	DS18B20 7					
	CALL DS		; CALLING DS_18B20 BUS RESET TO INIT NEW ROM			
CMN						
• ••••••						
	MOVLW	SKIP_ROM	; MATCH ROM COMMAND TO DS			
	CALL DS	_WRITE_BYTE	; MEM. FUNC. CMND TO WRITE A SINGLE BYTE			
;						
			IV ; ROM COMMAND TO START			
IEMP	CONVERT CALL DS		; MEM. FUNC. CMND TO WRITE A SINGLE BYTE			

;		.10	
, ;			
:	PAUSE	.10	
	CALL DS_		; CALLING DS_18B20 BUS RESET 2 INIT NEW ROM
CMN			
,			; MATCH ROM COMMAND TO DS
	CALL DS_	WRITE_BYTE	; MEM. FUNC. CMND TO WRITE A SINGLE BYTE
;		READ_SCR	ATCH ; ROM COMMAND TO READ SCRATC PAD
DATA		WRITE_BYTE	; MEM. FUNC. CMND TO WRITE A SINGLE BYTE
;	CALL DS_	READ_BYTE	; READ 8-BIT TMP_LSB DATA FROM SCRATCH PAD
;		L_BYTE RD_TEMP_I	LSB
PAD	CALL DS_	READ_BYTE	; READ 8-BIT TMP_MSB DATA FROM SCRATCH
;	CLRF H_B		
		RD_TEMP_1 KE_VALUE	MSB
;			
; PROO		••••••	
TROC	CLRF H_B		
	MOVFF CALL B2_	RD_TEMP_I BCD	LSB,L_BYTE
; MC			; SETTING LCD MESSAGE POSITION
CA	LL LCD_L	INE2W	; SETTING LCD LINE POSITION
	CALL DISI MAKE_VA	PLAY_TEMP LUE	;
;	GOTO LCE	DIAGNOSTIC	

CLRF	IR_FLAGS
CLRF	RMT_CMND
CLRF	RMT_ADDR
CLRF	IR_TIMER
CLRF	RMT_CMND_N
CLRF	RMT_ADDR_N
CLRF	INTCON1
CLRF	INTCON2
CLRF	INTCON3

CHK_MIN_HI

BSF	IR_FLAGS	S,NEW_BYTE
BSF	INTCON3,	3,INT1IE
BSF	INTCON,C	GIE
;##############	###################	+######################################
CALL	LCD_CLR	;

STNBY LOOP

MOVLW .5 CALL LCD_LINE1 BTFSC IR_FL ;

IR_FLAGS,STRT_PASS GOTO START_VALID

START IN VALID

MOVLW	'0'
CALL	DATA2LCD
GOTO	PRODUCE_BIT11

DATA2LCD

START_VALID

PRODUCE_BIT11

MOVLW '1'

CLRF TEMP3 Ν

CALL

RMT_ADDR,W
B'00010000'
0XFF
TEMP3,F
TEMP3,W

ADDLW 0X30 CALL DATA2LCD ****** **PRODUCE BIT10** CLRF TEMP3 MOVF RMT ADDR,W ANDLW B'00001000' ADDLW 0XFF RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD ***** PRODUCE_BIT9 CLRF TEMP3 MOVF RMT_ADDR,W B'00000100' ANDLW ADDLW **0XFF** TEMP3,F **RLCF** MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD ****** **PRODUCE BIT8** CLRF TEMP3 MOVF RMT_ADDR,W ANDLW B'0000010' ADDLW 0XFF **RLCF** TEMP3,F MOVF TEMP3,W ADDLW 0X30 DATA2LCD CALL ***** PRODUCE_BIT7 CLRF TEMP3 MOVF RMT ADDR,W ANDLW B'0000001' ADDLW **0XFF** TEMP3,F RLCF MOVF TEMP3.W

ADDLW 0X30 CALL DATA2LCD ***** **PRODUCE BIT6** CLRF TEMP3 MOVF RMT CMND,W ANDLW B'0100000' ADDLW 0XFF RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD **PRODUCE BIT5** CLRF TEMP3 MOVF RMT_CMND,W ANDLW B'00100000' ADDLW 0XFF RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD ***** **PRODUCE BIT4** CLRF TEMP3 MOVF RMT CMND,W B'00010000' ANDLW ADDLW **0XFF** RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 DATA2LCD CALL PRODUCE_BIT3 CLRF TEMP3 MOVF RMT_CMND,W ANDLW B'00001000' ADDLW 0XFF **RLCF** TEMP3,F MOVF TEMP3,W

ADDLW 0X30 CALL DATA2LCD PRODUCE_BIT2 **CLRF** TEMP3 MOVF RMT_CMND,W ANDLW B'00000100' ADDLW **0XFF** RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD PRODUCE BIT1 CLRF TEMP3 MOVF RMT_CMND,W ANDLW B'0000010' ADDLW 0XFF RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD ***** **PRODUCE BIT0** CLRF TEMP3 MOVF RMT_CMND,W B'0000001' ANDLW ADDLW **0XFF** RLCF TEMP3,F MOVF TEMP3,W ADDLW 0X30 CALL DATA2LCD OUT_PUT **IR_FLAGS,NEW BYTE** BTFSS GOTO OUT_PUT STNBY LOOP GOTO LCD ROUTINE TUNED FOR OSC @ 04 XT CONFIG : OSC_XT

LCD_LINE1			;CAALING LINE OF LCD LINE1
	MOVLW	0X80	;MOVE TO 1ST ROW, FIRST COLUMN
	MOVWF	ADDR	;SEETING ADDRESS
	CALL SET_	ADDR ;SEE	TING ADDRESS
•	RETLW	0X00	;END OF LCD LINE 1 ROUTINE
, LCD_LINE2			;CAALING LINE OF LCD LINE2
	MOVLW	0XC0	;MOVE TO 1ST ROW, FIRST COLUMN
	MOVWF	ADDR	;SEETING ADDRESS
			TING ADDRESS
•	RETLW	0X00	;END OF LCD LINE 2 ROUTINE
, LCD_LINE3			;CAALING LINE OF LCD LINE1
	MOVLW	0X94	;MOVE TO 1ST ROW, FIRST COLUMN
	MOVWF	ADDR	;SEETING ADDRESS
	_	,	TING ADDRESS
	RETLW	0X00	;END OF LCD LINE 1 ROUTINE
, LCD_LINE4			;CAALING LINE OF LCD LINE2
	MOVLW	0XD4	;MOVE TO 1ST ROW, FIRST COLUMN
	MOVWF	ADDR	;SEETING ADDRESS
			TING ADDRESS
•	RETLW	0X00	;END OF LCD LINE 2 ROUTINE
, LCD_CLR			;CAALING LINE OF LCD CLR
	MOVLW	0X01	;CLEAR DISPLAY
	MOVWF	ADDR	;SEETING ADDRESS
	CALL SET_	ADDR ;SEE	TING ADDRESS
	RETLW	0X00	;END OF LCD CLR ROUTINE
,LCD_LINE1V	N		;CAALING LINE OF LCD LINE1W
	ADDLW	0X80	;MOVE TO 1ST ROW, COLUMN W
	MOVWF	ADDR	;SEETING ADDRESS
	CALL SET_	ADDR ;SEE	TING ADDRESS
•	RETLW	0X00	;END OF LCD LINE1 W ROUTINE
,LCD_LINE2\	N		;CAALING LINE OF LCD LINE2W
	ADDLW	0XC0	;MOVE TO 2ND ROW, COLUMN W
	MOVWF	ADDR	;SEETING ADDRESS
	CALL SET_	ADDR ;SEE	TING ADDRESS
	RETLW	0X00	;END OF LCD LINE2 W ROUTINE

LCD_LINE3	ADDLW MOVWF	ADDR ;SEE	;CAALING LINE OF LCD LINE1W ;MOVE TO 1ST ROW, COLUMN W ;SEETING ADDRESS TING ADDRESS ;END OF LCD LINE1 W ROUTINE
LCD_LINE4V	ADDLW MOVWF	ADDR ADDR ;SEE 0X00	;CAALING LINE OF LCD LINE1W ;MOVE TO 1ST ROW, COLUMN W ;SEETING ADDRESS NG ADDRESS ;END OF LCD LINE1 W ROUTINE
_RESET MOVWI BSF E BCF E	F PORTC ; SET CALL DEL0 E	ET_8B ; LCI ; SEND TO THE LCD E I 5 ;	;CAALING LINE OF LCD RESET D INIT INSTRUCTION (FIRST) LCD VIA RB7RB0 LINE HIGH,
RETURN ; END OF RESET ROUTINE ;====================================			LIZATION ROUTINE ************************************
MOVWI BSF E BCF E MOVLW CALL MOVLW CALL MOVLW CALL MOVLW CALL	CALL _RE CALL _RE MOVLW SI F PORTC ; SET CALL D160 CALL CALL CALL CALL CALL CALL CALL CALL CALL	SET ; RES SET ; RES ET_4B_1L ; - ; SEND TO L E HIGH, US ; AND THI ; SEND CO ; CLEAR A ; SEND CO ; DISPLAY ; SEND CO ; SET CU ; SEND CO	

SET_ADDR ; CALLING LINE TO SET APPROPRIATE LCD DATA ADDRESS

BCF	Е	; FIX	POSITION ON LCD
BCF	RS	• • •	SEND COMMAND
MOVFADD	R,W	; SELECT A	ADDRESS FOR SENDING DATA TO
CALL CMN	ID2LCD;		
BSF	RS	;	

;

CMND2LCD

:_____

LCD

; CALLING LINE OF COMMAND 2 LCD

MOVWF LCD_CHAR ; SAVE BYTE TO WRITE TO LCD CLRF RS_VALUE ; REMEMBER TO CLEAR RS (CLEAR RS_VALUE) BCF RS ;

NOP

NOP

; VERY SHORT DELAY

GOTO WRITE2LCD ; GO TO COMMON CODE

;======= DATA2LCD ;CALLING LINE OF DATA 2 LCD

MOVWF LCD_CHAR ; SAVE BYTE TO WRITE TO LCD BSF RS_VALUE,0 ; REMEMBER TO SET RS (SET BIT 0 OF RS_VALUE) BSF RS ;

NOP ; VERY SHORT DELAY

; VERY SHORT DELAY

CALLING LINE FOR WRITE ON LCD

RETURN

CALL DEL50 CLRF PORTC ; CLEAR ALL OF PORT B (INPUTS AND OUTPUTS) MOVLW 0X00 ; SET UP TO ENABLE PORTB DATA PINS MOVWF TRISC ; ALL PINS (RB7..RB0) ARE BACK TO OUTPUTS BCF RS ; GUESS RS SHOULD BE CLEAR

BTFSC RS_VALUE,0 ; SHOULD RS BE CLEAR? (IS BIT 0 == 0?) BSF RS ; NO, SET RS NOP : VERY SHORT DELAY NOP : VERY SHORT DELAY ; TRANSFER MOST SIGNIFICANT NIBBLE (XXXX PORTION OF XXXXYYYY) MOVLW 0X0F ; SET UP MASK ANDWF PORTC,F ; CLEAR OLD RB7..RB4 MOVF LCD CHAR,W ; PUT BYTE OF DATA INTO W ANDLW 0XF0 ; MASK TO GIVE XXXX0000 IN W IORWF PORTC.F ; SEND TO RB7..RB4 WITHOUT CHANGING RB3..RB0 BSF E : PULSE THE E LINE HIGH. : VERY SHORT DELAY NOP NOP ; VERY SHORT DELAY BCF E : AND DROP IT AGAIN ; TRANSFER LEAST SIGNIFICANT NIBBLE (YYYY PORTION OF XXXXYYYY) MOVLW 0X0F ; SET UP MASK ANDWF PORTC,F ; CLEAR OLD RB7..RB4 SWAPF LCD CHAR,W ; MOVE LS NIBBLE OF DATA TO MS POSITION IN W : MASK TO GIVE YYYY0000 IN W ANDLW 0XF0 IORWF PORTC,F ; SEND TO RB7..RB4 WITHOUT CHANGING RB3..RB0 ; PULSE THE E LINE HIGH, BSF E NOP ; VERY SHORT DELAY NOP ; VERY SHORT DELAY BCF Ε ; AND DROP IT AGAIN NOP : VERY SHORT DELAY NOP : VERY SHORT DELAY

RETURN

;***** ALL THROUGH INDIRECT ADDRESSING ARE USED

INIT_PORT ; INITIALIZING CALLING LINE FOR 16F877A

	ING ADC (ADCON1 _DIGITAL		ING UP ADC PORT CONFIGURATIONS	
;	MOVLW (1< <pcfg< td=""><td>B'00000110'</td><td>· ,</td><td></td></pcfg<>	B'00000110'	· ,	
;	MOVWF	ADCON1	;DIRECTING ADCON1 REG,	
,	**************************************		*****	
D	MOVLW		;RA0, RA1 OPTIONAL ANALOG ALL	OTHER
D	MOVWF	TRISA;		
,	**************************************		*****	
D	MOVLW		;RB0, RA1 OPTIONAL ANALOG ALL	OTHER
D	MOVWF	TRISB;		
,	**************************************		*****	
D	MOVLW		;RB0, RA1 OPTIONAL ANALOG ALL	OTHER
D	MOVWF	TRISC;		
·**** '	**************************************	*********** ;	******	
;XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX				
D160U	JS ;			
	CLRF COUNT1	•		
	BSF COUNT1, 5	; DELAY 160	USECS	79

BSF COUNT1, 4 ;

DLOC)P DECFSZ	COUNT1, F	;
	GOTO	DLOOP	
	RETURN	DLOOI	•
			,
DEL2	55		
	MOVLW	0XFF	; DELAY 255 MS
	GOTO	D0	:
DEL2	00		
	MOVLW	D'255'	; DELAY 200MS
	GOTO	D0	· · · · · · · · · · · · · · · · · · ·
DEL1	00		
	MOVLW	D'200'	; DELAY 100MS
	GOTO	D0	•
DEL50	C		
	MOVLW	D'100'	; DELAY 50MS
	GOTO	D0	;
DEL2	C		
	MOVLW	D'40'	; DELAY 20MS
	GOTO	D0	;
DEL03	5		
	MOVLW	0X10	; DELAY 5.000 MS (4 MHZ CLOCK)
	GOTO	D0	;
DEL0			
	MOVLW	0X05	; DELAY 1.000 MS (4 MHZ CLOCK)
D0			
	MOVWF CO	UNT1	• ?
D1			
	MOVLW	0XC7	; DELAY 1MS
	MOVWF	COUNTA	•
	MOVLW	0X04	;
	MOVWF	COUNTB	•
DEL_(
	DECFSZ	COUNTA,F	;
	GOTO	\$+2	;
	DECFSZ	COUNTB,F	;
	GOTO	DEL_0	;
	DECFSZ	COUNT1,F	;
	GOTO	D1 ovoo	;
	RETLW	0X00	;

RESET DS1820 * DS RESET DOLOW PAUSE .250 ;TESTED OK WITH 16F876A @ 4 MHz PAUSE .480 DOHIZ .20 :TESTED OK WITH 16F876A @ 4 MHz PAUSE PAUSE .60 :TESTED OK WITH 16F876A @ 4 MHz **MOVFF** DS_PORT,W ANDLW 0X01 ; USE RA0 ONLY BANKSEL DUMMY1 MOVWF DUMMY1 .20 ;TESTED OK WITH 16F876A @ 4 MHz PAUSE .80 PAUSE TESTED OK WITH 16F876A @ 4 MHz MOVFF DUMMY1,W ; RESPONSE IN W REGISTER RETURN SEND DATA TO DS1820 (8 BIT) DS_WRITE_BYTE BANKSEL DUMMY1 **MOVWF** DUMMY2 : TRANSMISSION DATA : PREPARE 8-BIT COUNTER FOR 0X08 MOVLW SENDING DATA **MOVWF** DUMMY1 DS WRITE BIT DOLOW NOP RRCF DUMMY2,F : ROTATE DATA TO CARRY FLAG BTFSC STATUS.C : TEST CARRY FLAG DS_PORT,DS_BIT ; IF CARRY FLAG = "1" , SET DQ TO BSF HIGH PAUSE ;TESTED OK WITH 16F876A @ 4 MHz .10

PAUSE	.80	;TESTED OK WITH 16F876A @ 4 MHz					
	DQHIZ DECFSZ GOTO DS_W RETURN	,	; 8 TIMES ? ; NO, SEND AGAIN				
*********		******	*****				
, ; RECIEVE DATA FROM DS1820 (11 BIT TO IGNORE RESOLUTION BIT* ***********************************							
, DS_READ_E							
	MOVLF	0X08,DUMMY1	; RECIEVE 8-BIT DATA				
DS_READ_E							
	DQLOW		; MACRO OF DQ PIN TO LOW,				
THIS IS STA							
	NOP		; 10 MICROSECOND DELAY				
	NOP						
RECEIVING	DQHIZ		; BACK TO HIGH FOR				
KECEIVINU	NOP						
	MOVFDS_P	ORT W	; READ DATA				
	ANDLW		; GET DATA BIT 0 ONLY				
	ADDLW	0XFF	; MOVE DATA BIT 0 2 CARRY FLAG				
WITH ADD	METHOD		<i>,</i>				
	BANKSEL	DUMMY1					
	RRCF	DUMMY2,F	; MOVE DATA BIT 0 TO DUMMY BIT 7				
·*************************************	*********	******	*******				
; ; ;************	PAUSE ***********	,	DK WITH 16F876A @ 4 MHz ********************************				
	PAUSE	.65	;TESTED OK WITH 16F876A @ 4				
MHz							
	DECFSZ	DUMMY1,F	; LOOP 8 TIMES				
	GOTO DS_R	EAD_BIT	; READ AGAIN				
		MY2,W ; SA	VE DATA TO W REGISTER				
	RETURN						
·*************************************							
DISPLAY_T	EMP						
MOV							
MOV CALL	,	/_BCD_ASCII					
MOV		_DCD_ASCII					
CALL	/	A2LCD					
MOV							
	DATA2LCD						
MOV							
CALL	,	/_BCD_ASCII					
MOV	F H,W						
			83				

CALL DATA2LCD MOVF L,W CALL DATA2LCD MOVLW '.' ; CALL DATA2LCD

MOVFRES_BIT,W

CLRF H_BYTE MOVFF RES_BIT,L_BYTE CALL B2_BCD

R2,W
CONV_BCD_ASCII
H,W
DATA2LCD
L,W
DATA2LCD

MOVLW 0XDF CALL DATA2LCD

RETURN

```
B2 BCD
  BCF STATUS,C; CLEAR THE CARRY BIT
  MOVLW
       .16
       COUNT1
  MOVWF
  CLRF R0
  CLRF R1
  CLRF R2
******
LOOP16
  RLCF L_BYTE, F
  RLCF H_BYTE, F
  RLCF R2, F
  RLCF R1, F
  RLCF R0, F
  DECFSZ
       COUNT1, F
```

GOTO ADJDEC						
RETLW 0						

ADJDEC	LW R2					
	VF FSR1	r				
	ADJBCD					
-						
	LW R1	r				
	MOVWF FSR1L					
-	CALL ADJBCD					
	LW R0	r				
	WF FSR1					
	ADJBCD	1.4				
GOTC		-				
•*************************************						
ADJBCD						
MOVI		1,W				
ADDL						
	MOVWF TEMP1					
BTFS		P1,3 ; TEST IF	RESULT > 7			
MOVV						
MOVF INDF1,W		1,W				
ADDL	W 0X30	0X30				
MOVV	WF TEMI	TEMP1				
BTFS	C TEMI	EMP1,7; TEST IF RESULT > 7				
MOVV	WF INDF	1 ; SAV	E AS MSD			
RETL	W 0					
;XXXXXXXX	XXXXXXXXX	XXXXXXXXX	XXXXXXXXXXXXXXXXX			
·*************************************	****MATH RO	OUTINE BCD '	TO ASCII CONVERSION**************			
;XXXXXXXX	XXXXXXXXX	XXXXXXXXX	XXXXXXXXXXXXXXXX			
CONV_BCD_	_ASCII		;CALLING LINE OF BCD TO ASCII			
	MOVWF	TEMP	GETTING BCD NUMBER IN TEMP REGISTER			
	SWAPF	TEMP,W	;SWAPPING NIBBLES OF TEMP BYTE			
		,				
	ANDLW	B'00001111'	;MASKING HIGH NIBLE ONLY			
0X30	ADDLW	0X30	;MAKING THE VALUE 2 ASCII BY ADDING			
	MOUNT	TT				
	MOVWF	Н	;STORING HIGH NIBLE ASCII VALUE			
	MOVFTEMP,W		;TAKING LOWER NIBBLE			

ANDLW B'00001111' ;MASKING LOWER NIBBLE ONLY ADDLW 0X30 ;MAKING THE VALUE 2 ASCII BY ADDING 0X30

MOVWF L ;STORING LOW NIBLE ASCII VALUE

RETURN ;RETURN LINE FOR BCD 2 ASCII SUBROUTINE

MAKE_VALUE

CLRF RES_BIT MOVFRD_TEMP_LSB,W ANDLW B'00001111' MOVWF RES_BIT

RRCF RD_TEMP_MSB,F RRCF RD_TEMP_LSB,F RRCF RD_TEMP_MSB,F RRCF RD_TEMP_LSB,F RRCF RD_TEMP_MSB,F RRCF RD_TEMP_LSB,F RRCF RD_TEMP_MSB,F RRCF RD_TEMP_LSB,F

RESU_

MOVLW	0X7F
ANDWF	RD_TEMP_LSB,F
RETURN	

RES_TABLE

ADDWF	PCL,F
RETLW	'0'
RETLW	'1'
RETLW	'1'
RETLW	'2'
RETLW	'2'
RETLW	'3'
RETLW	'3'
RETLW	'4'
RETLW	'5'
RETLW	'6'
RETLW	'ő'
RETLW	'7'
RETLW	'8'
	0

RETLW '8' RETLW '9' '9' RETLW ACQR_LO_T CLRF IR_TIMER BCF PIR1,TMR1IF BSF IR_FLAGS, IR_ERROR MOVLW B'00111000' MOVWF **T1CON** BSF T1CON,0 INIT_LENGTH_LO SETF TMR1H ;ADJUSTING VALUUE FOR T=600 MICRO SECS; MOVLF SIRC_ON_T,TMR1L;ADJUSTING VALUUE FOR T=600 MICRO SECS: IR STIL LO BTFSC PIR1,TMR1IF GOTO UPDT_IR_LEN_LO BTFSSREMOTE GOTO IR STIL LO IR_RTN_LO_2_HI BCF T1CON.0 BCF PIR1,TMR1IF MOVFIR TIMER,W BTFSC STATUS.Z RETURN BCF IR_FLAGS, IR_ERROR RETURN ***** UPDT_IR_LEN_LO INCF IR_TIMER,F BCF PIR1,TMR1IF GOTO INIT_LENGTH_LO

ACQR_HI_T CLRF TEMP2 BCF PIR1,TMR1IF BSF IR_FLAGS, IR_ERROR MOVLW B'00111000' **MOVWF** T1CON BSF T1CON,0 INIT_LENGTH_HI SETF TMR1H ADJUSTING VALUUE FOR T=600 MICRO SECS; MOVLF SIRC OFF T,TMR1L;ADJUSTING VALUUE FOR T=600 MICRO SECS : IR_STIL_HI BTFSC PIR1,TMR1IF GOTO UPDT_IR_LEN_HI BTFSC REMOTE GOTO IR_STIL_HI IR RTN HI 2 LO BCF T1CON.0 BCF PIR1,TMR1IF MOVFTEMP2,W BTFSC STATUS,Z RETURN BCF IR_FLAGS, IR_ERROR RETURN UPDT_IR_LEN_HI INCF TEMP2,F BCF PIR1,TMR1IF GOTO INIT LENGTH HI

END

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